Product Change Notification - GBNG-02AHWK946

Date:

09 Aug 2019

Product Category:

Notification subject:

CCB 3857 Final Notice: Implement Microchip Part Aging Policy, Combination Rules, Recertification, Label and Packing Changes for selected Microsemi (SNR, PM, PoE and CBU) products.

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

Note 1: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Note 2: As part of the integration process additional products may be identified that were not part of the original list.

Description of Change:

Implement Microchip Part Aging Policy, Combination Rules, Recertification, Label and Packing Changes for selected Microsemi (SNR, PM, PoE and CBU) products within the Microsemi subsidiaries Microsemi Solutions Sdn.Bhd. which includes formerly Sensors, Power Management, Power over Ethernet and Communications Business Unit / PMC Sierra.

Change in Part Aging Policy

Change in Combination Rules

Change in Recertification Program

Change in Reel/Bag/Inner/Outer Shipping/MSL Labels

Change to Packing Method

Pre Change:

Using Microsemi's packing process.

Post Change:

Using Microchip's packing process.

Pre and Post Change Summary:

NOTE: See attached Packing Pre and Post Changes for the changes of the following.

Details	**PRE CHANGE (MSCC)**	**POST CHANGE (Microchip)**
Part Aging Policy	- Microsemi may ship parts up to 24 months (2 years). - Parts older than 24 months (2 years) will shipped only after prior approval from customer.	- Microchip may ship parts up to 48 months (4 years). - Parts older than 24 months (2 years) old will be recertified prior to shipment.
Combination Rule	- 1 device, 2 date codes	- 1 device, 3 date codes
Recertification Program	- Recertification of solderability at 3 years and solderability and	- Parts older than 24 months (2 years) old will be recertified

		electrical test at 5 years.	prior to shipment
Label	**Inner Shipping Label**	- Microsemi branded label - Without 2D bar code	- Microchip branded label - With 2D bar code
	Outer Shipping Label	- No standard shipping label - Without 2D bar code	- Microchip standard label - With 2D bar code
	ESD Caution Label	With ESD caution label on reel	Without ESD caution label on reel
	MSL Caution Label	- With Moisture Sensitivity Level label on moisture barrier bag for MSL 1 products - With MSL caution label being attached on MBB for MSL 3 products - Calculated shelf life of 12 months for MSL 3 products	- Without Moisture Sensitivity Level label on moisture barrier bag for MSL 1 products - Pre-printed MSL caution label on MBB for MSL 3 products - Calculated shelf life of 24 months for MSL 3 products
	Moisture Sensitivity Identification Label	No Moisture Sensitivity Identification (MSID) label on inner carton	With Moisture Sensitivity Identification (MSID) label on inner carton for moisture sensitive device
Packing	**Method**	Use the kraft to fill in outer carton	Use bubble sheet to fill in outer carton
	Material	- MBB no Desiccant - SSB + Desiccant	- MSL1 product - use of static sensitive bag (SSB) without desiccant and HIC
	Desiccant	1, 2, or 4 desiccants per bag depending on packaging site	2 desiccants per bag for all products
	Humidity Indicator Card (HIC)	Cobalt Dichloride free or Cobalt free	Cobalt free
	Moisture Barrier Bag / Static Shield Bag	See attached Pre and Post Changes	
	Inner/Outer Carton	See attached Pre and Post Changes	

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by standardizing the packing method as part of the integration of Microsemi and Microchip.

Change Implementation Status:

In Progress

Earliest Implementation Date:

November 01, 2019

Note: The earliest implementation date is the earliest date that we may implement any combination of the changes listed in this PCN as we will not implement any of the proposed changes prior to this date. After the earliest implementation date these changes may occur to any product over the course of many months depending on inventory levels and business conditions.

Time Table Summary:

	August 2019					->	November 2019				
Workweek	31	32	33	34	35		44	45	46	47	48
Final PCN Issue Date		X									
Estimated Implementation Date							X				

Method to Identify Change:

Traceability, label, inner and outer boxes.

Contact Microchip:

You may contact your local Microchip Sales and Distribution. Contact information is also provided on the attached Frequently Asked Questions (FAQ).

If applicable, please also copy your local Microchip field sales and/or field quality representative.

Revision History:

August 09, 2019: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

Frequently Asked Questions Microsemi November.pdf
PCN_GBNG-02AHWK946_Affected CPN.pdf
PCN_GBNG-02AHWK946_Pre_and_Post_Changes.pdf
PCN_GBNG-02AHWK946_Affected CPN.xlsx

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to change your PCN profile, including opt out, please go to the PCN home page select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

GBNG-02AHWK946 - CCB 3857 Final Notice: Implement Microchip Part Aging Policy, Combination Rules, Recertification, Label and Packing Changes for selected Microsemi (SNR, PM, PoE and CBU) products.

Affected Catalog Part Number (CPN)

PCN_GBNG-02AHWK946
CATALOG_PART_NBR
PAS6413A-F3GC
PD69200C-017201
PD70201ILQ-TR
PD81000-027301
PD70100ILD-TR
PD70101ILQ-TR
PD69108FILQ-TR
PD69104ILQ-TR
PD69100C-024801-TR
PD69100C-023901-TR
PD69104B1FILQ-TR
WP441W6A1-500-NFEI
PD69108ILQ-TR
PD69101ILQ-TR
PD69100C-026301
PD70200ILD-TR
PD69104B1ILQ-TR
WP32C0W5NHEI-450B2
WP3061W8NHEI-250B1
WP3232M5NELI-320B2
PD69100R-026515
PD69200C-018813
PD69200C-016721-TR
PD39100C-026381
PD69200C-021413-TR
PD69200C-015101-TR
PD69100R-026303
PD69200R-017203
PD39100C-025891
PD39100R-0113
PD69200C-017213
PD39100R-011320
PD69100C-026392
PD69100C-026380
PD69208T4ILQ-TR-LE
PD69200C-019027
PD69200R-034300
PD69100C-024101
WP441R6A1-500-EFEI
PD69000AC-0415
PD69000DC-0100
PD69012
PD69100C-023901
PD69000AC-0411
PD69000AC-0301

Affected Catalog Part Number (CPN)

PD69200C-012101
PD69100C-026301-TR
PD69000AC-0414
PD69100R-0233
PD69100R-0122
PD69100R-023950
PD69000AC-0413
PD69000DC-0415
PD69000DC-0303
PD69008
PD69000DC-0416
PD69000DC-0211
PD69100R-023903
PD81000-027302
PD69100R-023603
PAS5211A-F3EI
WP34C2R4EFEI-400B2
PD69100C-023701
PD69200R-012103
PD69100C-0233
PD69000DC-0300
PD70211ILQ-TR
PD69000DC-0202
PD69100C-023204
PD69100C-024801
PD69200R-021120-TR
PD69000DC-0417
PD69100R-026504
PD69000AC-0211
WP3232M6NFEI-320B2
PD69100R-025503
WP32C2M6NELI-450B2
PD69000AC-0404
PD69000DC-0301
PAS7400B-NGI
PD69200C-018818
PD69000DC-0404
PD69000AC-0412
PD69000AC-0202
WIN840W6NHEI-300A1
PAS6512B-F3GI
PD81101ILQ-TR-LE
PD69100C-026001
PD69200R-021120
UFE412-M4
PAS5201-A0
WP32C2W3EFEI-320B2

Affected Catalog Part Number (CPN)

PD69200C-021019-TR
PD69100C-024201
WIN860M6NHEI-300A1
WP32C2W6NFEI-400B2
WP441R6A1-500-NFEI
WP441W6A1-500-EFEI
PD69200R-017217
PD69100C-024901
PAS5201-L0
PAS6401B-F3GI
PAS6511B-F3GI
PD69200C-017221
WP33C2A1EFEI-450B2
WP32C2A4EFEI-400B2
PD69200C-016101
PAS7401B-PGI
PD69200C-021019
UFE412-T1
WP3160W6NFEI-320B1
PD69200R-017223
PD69200C-021119
PD64004AH
WP3161W6NFEI-320B1
WP441W6A1-400-EFEI
WP3161W1EFEI-320B1
PD69200C-018818-TR
PAS6511B-F3EI
WP32C2M6NHEI-400B2
PD39100C-025881
WP3160W3NFEI-320B1
WIN2A3NHEI-250A1-2
WIN2A3NHEI-250A1
WP3392D4NFEI-320B2
WP3232M5NHEI-320B2
WP3161W6NHEI-400B1
UFE412-T2
WP34C2R4NFEI-400B2
PD69200C-016701
WP3061W1NHEI-250B1
PD69100R-026503
PD81000-028101
WP3161R4NFEI-320B1
WP3362D4NFEI-320B2
PD69100C-0232-TR
PD69100R-026311
WP441W6A1-400-NFEI
PD81000-028103

Affected Catalog Part Number (CPN)

PD69200C-021413
PD69100C-026598
PD69100C-026501
PD69200C-016501
PD39100C-026501
PD69101ILQ-13155TR
WIN867R4NHEI-330A1
PD69200R-015103
PD69000DC-0210
PD69208MILQ-TR-LE
PD69000AC-0210
PD69100C-023601
PD69100C-025501
PAS6411B-F3GI
WIN860M6NHEI-350A1
WP34C2R6EFEI450B2R
WIN847W6NHEI-250A1
PD69000DC-0414
PD70224LILQ-TR
PD70210ALILQ-TR
PD69000AC-0300
PD69000AC-0410
WP33C2D4NFEI-450B2
PD82000-021200
WIN867M6NHEI-300A1
PD69200C-016121
PD69100C-026516
PD69100C-025880
PD69100R-026611
WP34C2R6NFEI450B2R
PD69100C-023290
PD69204T4ILQ-TR-LE
PD69200C-021119-TR
PD69000DC-0400
PD69000DC-0401
PD69000DC-0411
PD69100C-0122
PD70210AILD-TR
WIN847W3NHEI-250A1
WP3161F5NFEI-320B1
PD69200R-018703
PD69200C-016721
PD69100C-026501-TR
WP3061W2NHEI-250B1
WP32C2M6NELI-400B2
PD70224ILQ-TR
PD69200C-015101

GBNG-02AHWK946 - CCB 3857 Final Notice: Implement Microchip Part Aging Policy, Combination Rules, Recertification, Label and Packing Changes for selected Microsemi (SNR, PM, PoE and CBU) products.

Affected Catalog Part Number (CPN)

PD69200C-018701
WP3161D4NFEI-400B1
PD70210ILD-TR
PD69200R-016103
UFE412-T4
PD69200R-021126
PD69200R-021126-TR
PD69200R-016703
PD39100C-024001
PD69100R-024803
WP3161EFEI-400B1
AA540F-01-1016-G-LF
AA540F-01-1416-G-LF
AA550C2-01-1104-G-LF
AA568C1-01-1016-G-LF
AA576B-01-1612-GLFTR
AA585B-01-2548-GLF-TR
AA598D1-01-1416-G-LF
AA623B-01-2724-GLFTR
AA800A_V1R6-01-1416-GLF-13165-TR
AAC243E-S8A-G-LF-TR
AAP661AS-M5A-GLF-TR
AAP661BS-M5A-GLF-TR
AAP661CS-M5A-GLF-TR
AAP803A1
AAP803A3
IPS18I-SO-G-LF-TR
IPS21I-SO-G-LF-TR
LX13084AILQ-TR
LX27901ID-13154-TR
LX27901ID-TR
LX3301AQPW
LX3301AQPW-13172-TR
LX3301AQPW-TR
LX3302AQPW
LX3302AQPW-TR
LX7104ISF-TR
LX7165-01CSP-TR
LX7165-02CSP-TR
LX7165-03CSP-TR
LX7165-05CSP-TR
LX7167ACLD-TR
LX7175CLD-TR
LX7167CLD-TR
LX7176ACLQ-TR
LX7176CLQ-13162-TR
LX7178-01CSP-TR

Affected Catalog Part Number (CPN)

LX7180A-01CLQ-TR
LX7180A-11CLQ-TR
LX7180A-21CLQ-TR
LX7186AILU-TR
LX7180A-31CLQ-TR
LX7188ILU-TR
LX7219-01ILQ-TR
LX7219-02ILQ-TR
LX7220-03ILQ-TR
LX802AQDB-TR
LX802QDB-TR
LX8213-00ISE-TR
LX7309ILQ-TR
LX8213-12ISE-TR
LX8213-33ISE-TR
LX8233ILQ-TR
LX8237ILQ-TR
LX8237ILQ-TR-V2R3
LX8237ILQ-TR-V3R2
LX8240ILD-TR
NX7101IDMTR
NX7102IDETR
NX2124CSTR
PD69200C-021819
PD69200R-034600
NX9548ILQ-TR
PD69200R-021020
LX8259-03ILQ-TR

Part Aging Policy, Combination Rules, Recertification, Label and Packing Changes for selected Microsemi (SNR, PM, PoE-IC, PoE-MCU, CBU) products.

CCB NO. 3857

Label and Packing material change of SNR, PM

Part Aging
SNR/PM

PRE CHANGE	POST CHANGE
Microsemi may ship parts up to 24 months (2 years). Parts older than 24 months (2 years) will shipped only after prior approval from	Microchip may ship parts up to 48 months (4 years). Parts older than 24 months (2 years) old will be recertified prior to shipment. The requirement will be applied for both automotive and commercial. Reason: Material sets used to manufacture integrated circuits have shown no degradation in solderability, moisture sensitivity or reliability of products after 48 months. *For more information related to Microchip's part aging strategy, please visit the following link on our website: Component Age Policy*

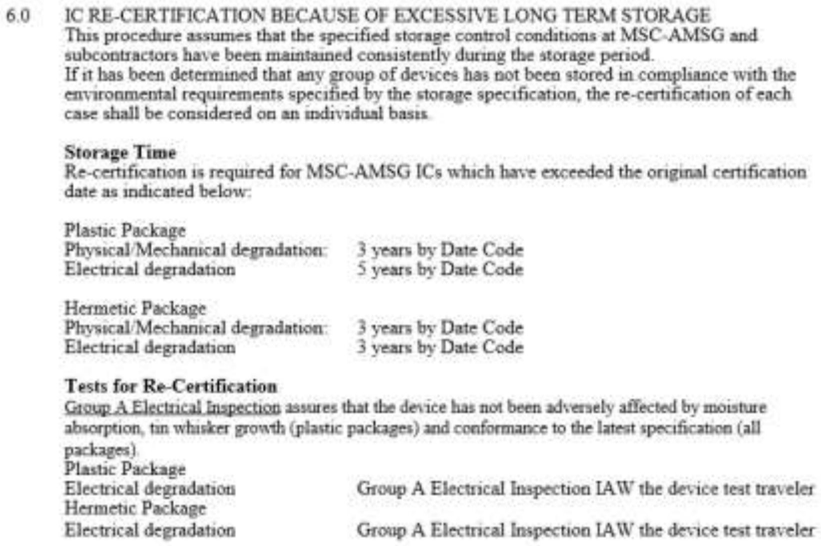
Combination Rule
SNR/PM

PRE CHANGE	POST CHANGE
•1 Device.	•1 Device.
•2 Date codes.	**•3 Date codes.**
•No limit to number of production lots follow date code combination rule.	•No limit to number of production lots follow date code combination rule.
•1 Assembly Site.	•1 Assembly Site.
•1 Test Site.	•1 Test Site.
•1 Wire Material.	•1 Wire Material.
•No limit for Die Revision, Die ID, Fab Revision, Different T/C, and test flow.	•No limit for Die Revision, Die ID, Fab Revision, Different T/C, and test flow.

Recertification Program SNR/PM

PRE CHANGE

Recertification of solderability at 3 years and solderability and electrical test at 5 years.



6.0 IC RE-CERTIFICATION BECAUSE OF EXCESSIVE LONG TERM STORAGE

This procedure assumes that the specified storage control conditions at MSC-AMSG and subcontractors have been maintained consistently during the storage period.
If it has been determined that any group of devices has not been stored in compliance with the environmental requirements specified by the storage specification, the re-certification of each case shall be considered on an individual basis.

Storage Time
Re-certification is required for MSC-AMSG ICs which have exceeded the original certification date as indicated below:

Plastic Package
Physical/Mechanical degradation: 3 years by Date Code
Electrical degradation 5 years by Date Code

Hermetic Package
Physical/Mechanical degradation: 3 years by Date Code
Electrical degradation 3 years by Date Code

Tests for Re-Certification
Group A Electrical Inspection assures that the device has not been adversely affected by moisture absorption, tin whisker growth (plastic packages) and conformance to the latest specification (all packages).
Plastic Package
Electrical degradation Group A Electrical Inspection IAW the device test traveler
Hermetic Package
Electrical degradation Group A Electrical Inspection IAW the device test traveler

POST CHANGE

Parts older than 24 months (2 years) old will be recertified prior shipment. It may include one or more of the following: inspections, retest, rescanning and repacking of parts.

WIP: Original datecode exceeds 22 months and it is not over 3 years 10 months.

FG : Original datecode exceeds 23 months and it is not over 4 years.

RMA : Original datecode exceeds 24 months and and it is not over 4 years.

Reel/Bag/Inner Label
SNR, PM

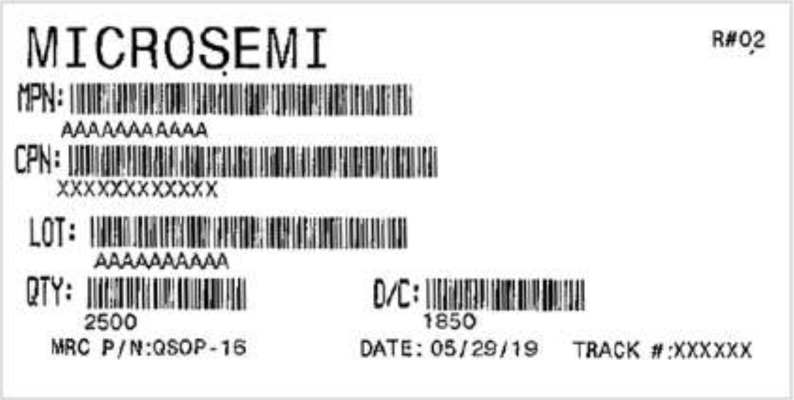
PRE-CHANGE

CIRTEK PHILLIPPINE

MICROCHIP
DEVICE : AA550C2
LOT # : T97483-1
PKGE : SOT-143
QTY. : 7,500
DEV . CODE : 65175
DATE CODE : 1847

QC / QA
Tested Good

MRC SAN JOSE



MICROSEMI R#02
MPN:
AAAAAAAAAAA
CPN:
XXXXXXXXXXXX
LOT:
AAAAAAAAAA
QTY: 2500
D/C: 1850
MRC P/N:QSOP-16
DATE: 05/29/19
TRACK #:XXXXXX

SPEL INDIA

Microsemi Corporation
MANUFACTURER P/N AAC243E-S8A-G-LF-TR
Pb-free
DATE CODE 1430
PKG TYPE:
8 LD-SO
OPERATOR ID# :
792 - 140815190001
LOT NO T58145
(2014070223)
QTY 2500

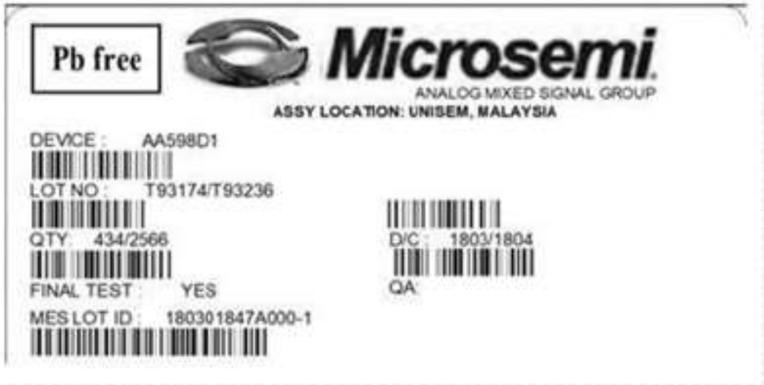
UNISEM CHINA

Pb-free/RoHS
Microsemi
ANALOG MIXED SIGNAL GROUP
ASSY LOCATION CHINA
DEVICE:LX7165-01CSP-TR
LOT NO.:CH00750-1
QTY:3000
D/C:1810A
FINAL TEST:NO
QA:
REEL ID:MIS1810001A000-10

Reel/Bag/Inner Label
SNR, PM

PRE-CHANGE

UNISEM Malaysia



Pb free

Microsemi

ANALOG MIXED SIGNAL GROUP

ASSY LOCATION: UNISEM, MALAYSIA

DEVICE : AA598D1

LOT NO : T93174/T93236

QTY : 434/2566

D/C : 1803/1804

FINAL TEST : YES

QA:

MES LOT ID : 180301847A000-1

UTAC CHINA

Microsemi

PART NO.: LX13084AILQ-TR

Pb - Free

LOT NUMBER: SG16815

DATE CODE : 1646

QTY : 3000

COO: CHINA

A005292800

A005292801

UTAC THAILAND

MICROSEMI CORPORATION

BOX no: 1 OF 6

PT NO: AAWPG0016.1

QTY: 3500

DEVICE: AAP661CS-M5A-GLF-TR

LOT1: T49348

DC1: 1320

DC2:

Reel/Bag/Inner Label
SNR, PM

POST CHANGE

(1P) CATALOG P/N: **ABCDEFGKIJKL-BB-CC-DDDD-EEEEE-FF**

(1T) LOT NO.: **114601899000MTAI**

MSL: 3/260 C
PKG: TFBGA
LEAD: 48

(Q) QTY
2500

(P) CUST. P/N: **ABCDEFGH IJKLMNO PQRSTUV REV A**

MPC: **ABCDEFGHKLMNO**

SEAL DATE: MM/DD/YY
WAFER QTY: -
WAFER REV: -
RECERT D/C: -
WAFER LOT: -

D/C	QTY
1407	250
1408	1000
1509	1250

ID#:(001) TRACE CODE: 1407B1R,1408B1Q,1509A3R

MADE IN THAILAND

Reel/Bag/Inner Label
SNR, PM

PRE CHANGE																					POST CHANGE		
CIRTEK			MRC			SPEL			UNISEM CHINA			UNISEM MALAYSIA			UTAC CHINA			UTAC THAILAND			MCHP		
Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode
MICROCHIP	Y	N	MICROSEMI	Y	N	Microsemi Corporation	Y	N	Microsemi Logo	Y	N	Microsemi Logo	Y	N	Microsemi Logo	Y	N	MICROSEMI CORPORATION	Y	N	Microchip Logo	Y	N
DEVICE	Y	N	CPN	Y	Y	MANUFACTURER P/N	Y	Y	DEVICE	Y	Y	DEVICE	Y	Y	PART NO	Y	Y	DEVICE	Y	Y	(1P) CATALOG P/N	Y	Y
LOT#	Y	N	LOT	Y	Y	LOT NO	Y	Y	LOT NO	Y	Y	LOT NO	Y	Y	LOT NUMBER	Y	Y	LOT1	Y	Y	(1T) LOT NO	Y	Y
QTY	Y	N	QTY	Y	Y	QTY	Y	Y	QTY	Y	Y	QTY	Y	Y	QTY	Y	Y	QTY	Y	Y	(Q) QTY	Y	Y
DATE CODE	Y	N	D/C	Y	Y	DATE CODE	Y	Y	D/C	Y	Y	D/C	Y	Y	DATE CODE	Y	Y	DC1	Y	Y	D/C	Y	N
-	-	-	-	-	-	Pb Free Symbol	Y	N	Pb-free	Y	N	Pb Free Symbol	Y	N	Pb Free Symbol	Y	N	-	-	-	Pb Free Symbol	Y	N
-	-	-	-	-	-	-	-	-	RoHS	Y	N	-	-	-	-	-	-	-	-	-	RoHS Symbol	Y	N
-	-	-	-	-	-	-	-	-	ASSY LOCATION	Y	N	ASSY LOCATION	Y	N	COO		Y	-	-	-	MADE IN	Y	N
PKGE	Y	N	-	-	-	PKG TYPE	Y	N	-	-	-	-	-	-	-	-	-	-	-	-	PKG	Y	N
-	-	-	-	-	-	-	-	-	FINAL TEST	Y	N	FINAL TEST	Y	N	-	-	-	-	-	-	-	-	-
QC/QA Tested Good	Y	N	-	-	-	-	-	-	QA	Y	N	QA	Y	N	-	-	-	-	-	-	-	-	-
DEV. CODE	Y	N	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
-	-	-	MPN	Y	Y	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	MPC	Y	N
-	-	-	MCR P/N	Y	N	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-

Reel/Bag/Inner Label
SNR, PM

PRE CHANGE																					POST CHANGE		
CIRTEK			MRC			SPEL			UNISEM CHINA			UNISEM MALAYSIA			UTAC CHINA			UTAC THAILAND			MCHP		
Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode
-	-	-	DATE	Y	N	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
-	-	-	TRACK#	Y	N	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
-	-	-	-	-	-	OPERATOR ID#	Y	N	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
-	-	-	-	-	-	-	-	-	REEL ID	Y	Y	-	-	-	-	-	-	BOX no.	Y	N	ID#	Y	Y
-	-	-	-	-	-	-	-	-	-	-	-	MES LOT ID	Y	Y	-	-	-	PT NO	Y	Y	-	-	-
-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	DC2	Y	Y	-	-	-
-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	QTY (per D/C)	Y	N
-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	eCAT Symbol	Y	N
-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	(P) CUST. P/N	Y	Y
-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	MSL	Y	N
-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	SEAL DATE	Y	N
-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	TRACE CODE	Y	N
-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	China RoHS Symbol	Y	N
-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	LEAD	Y	N
-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	WAFER QTY	Y	N
-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	WAFER REV	Y	N
-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	RECERT D/C	Y	N

Outer Label
SNR, PM

PRE-CHANGE

UNISEM MALAYSIA

FROM: MICROSEMI CORPORATION
C/O UNISEM (M) BERHAD
IPC WAREHOUSE
NO.1 PERSIARAN PULAI JAYA

TO: KSR Electronic Systems Ltd
Heol y Ddraig, Penllergaer Business Park
Penllergaer, Swansea SA4 9HL UNITED
KINGDOM UNITED KINGDOM

(4S) PKG TYPE : 16QSOP-M(SN)

DEV: AA800A_V1R6-01-1416-GLF-13165-TR

(Q) QTY: 30000

(14K) P.O.#: P000070

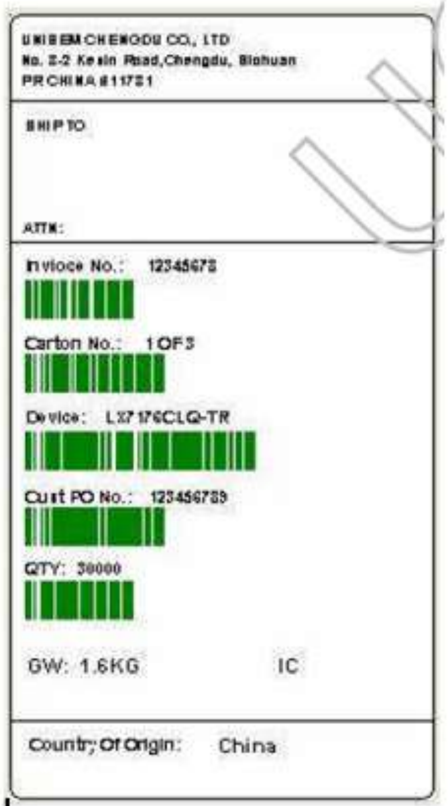
DATE CODE: 1915

NET WEIGHT 9.20 KG

PACKAGE COUNT 1OF1

GROSS WEIGHT 10.50 KG

UNISEM CHINA



UNISEM CHENGDU CO., LTD
No. 2-2 Kexin Road,Chengdu, Sichuan
PR CHINA 611731

SHIP TO

ATTN:

Invoice No.: 12345678

Carton No.: 1 OF 3

Device: LX7176CLQ-TR

Cust PO No.: 123456789

QTY: 30000

GW: 1.6KG IC

Country Of Origin: China

UTAC CHINA

FROM:

UTAC Dongguan Ltd.

TO: Jabil Circuit de Mexico
S.de R.L.de C.v. Almacen General Av.
Valdepenas 1993, Col Lomas de Zapopan.
Zapopan Jalisco 45130 Mexico
Jalisco 45130 MEXICO

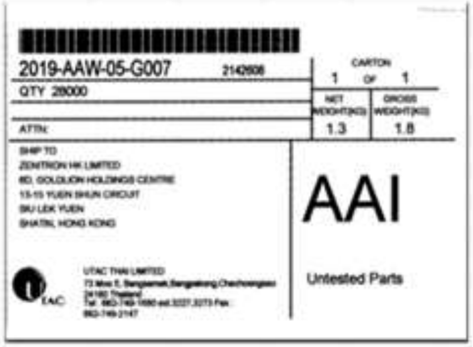
Inner BOX qty: 4

1000949020

BOX: 1 OF 7

DN NO: 80560141

UTAC THAILAND



2019-AAW-05-G007 2142606

QTY 28000

ATTN:

CARTON 1 OF 1

NET WEIGHT(KG) 1.3

GROSS WEIGHT(KG) 1.8

SHIP TO
ZENITRON HK LIMITED
8D, GOLDLION HOLDINGS CENTRE
13-15 YUEN SHUN CIRCUIT
SIU LEK YUEN
SHATIN, HONG KONG

AAI

UTAC THAI LIMITED

Untested Parts

GARDEN GROVE

No standard Shipping label

Outer Label
SNR, PM

POST CHANGE

B-HK-PHC-S2269812

SHIP TO:
PHILIPS CONSUMER ELECTRONICS
WILSON LOGISTIC CT, 6/F
PHILIPS IND BLDG., 24-28 KUNG
KUNG YIP ST, KWAICHUNG
HONG KONG

Cust. P/N: 3139 227 01992

Catalog P/N: DSPIC33FJ128MC510T-I/PTC22

PO#: 55016400/2

SO #: 472542/26

Qty: 200000

Hong Kong
10-21-2010
(mm-dd-yyyy)

Carton 1
of 20
19.5 kgs

Outer Label
SNR, PM

PRE CHANGE												POST CHANGE		
UNISEM CHINA			UNISEM MALAYSIA			UTAC CHINA			UTAC THAILAND			MCHP		
Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode
Ship from address	Y	N	Ship from address	Y	N	Ship from address	Y	N	Ship from address	Y	N	-	-	-
Ship to address	Y	N	Ship to address	Y	N	Ship to address	Y	N	Ship to address	Y	N	SHIP TO	Y	N
Invoice No.	Y	Y	-	-	-	-	-	-	-	-	-	-	-	-
Carton No.	Y	Y	-	-	-	BOX … OF …	Y	N	CARTON … OF …		N	No of carton	Y	N
Device	Y	Y	DEV	Y	Y	-	-	-	-	-	-	Catalog P/N	Y	Y
Cust PO No.	Y	Y	(14K) P.O.#	Y	Y	-	-	-	-	-	-	PO#	Y	Y
QTY	Y	Y	(Q) QTY	Y	Y	-	-	-	QTY	Y	N	Qty	Y	Y
GW	Y	N	GROSS WEIGHT	Y	N	-	-	-	GROSS WEIGHT	Y	N	Gross Weight	Y	N
Country of Origin	Y	N	-	-	-	-	-	-	-	-	-	-	-	-
-	-	-	(4S) PKG TYPE	Y	Y	-	-	-	-	-	-	-	-	-
-	-	-	DATE CODE	Y	Y	-	-	-	-	-	-	-	-	-
-	-	-	NET WEIGHT	Y	N	-	-	-	NET WEIGHT	Y	N	-	-	-
-	-	-	PACKAGE COUNT	Y	N	-	-	-	-	-	-	-	-	-
-	-	-	-	-	-	Inner BOX qty	Y	N	-	-	-	-	-	-

Outer Label
SNR, PM

PRE CHANGE												POST CHANGE		
UNISEM CHINA			UNISEM MALAYSIA			UTAC CHINA			UTAC THAILAND			MCHP		
Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode
-	-	-	-	-	-	DN NO	Y	N	-	-	-	-	-	-
-	-	-	-	-	-	-	-	-	-	-	-	Cust P/N	Y	Y
-	-	-	-	-	-	-	-	-	-	-	-	SO#	Y	Y
-	-	-	-	-	-	-	-	-	-	-	-	(mm-dd-yyyy)	Y	N
-	-	-	-	-	-	-	-	-	-	-	-	eCAT Symbol	Y	N
-	-	-	-	-	-	-	-	-	-	-	-	Pb Free Symbol	Y	N
-	-	-	-	-	-	-	-	-	-	-	-	RoHS Symbol	Y	N
-	-	-	-	-	-	-	-	-	-	-	-	China RoHS Symbol	Y	N
-	-	-	-	-	-	-	-	-	-	-	-	Ship Number	Y	Y
-	-	-	-	-	-	-	-	-	-	-	-	2D barcode	N	Y

ESD Caution label on Reel
SNR, PM

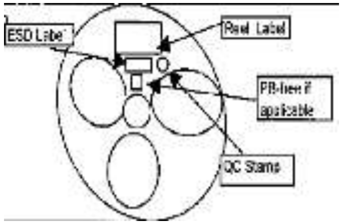
PRE CHANGE

UNIC

UNIS 13"

UTAC-TH

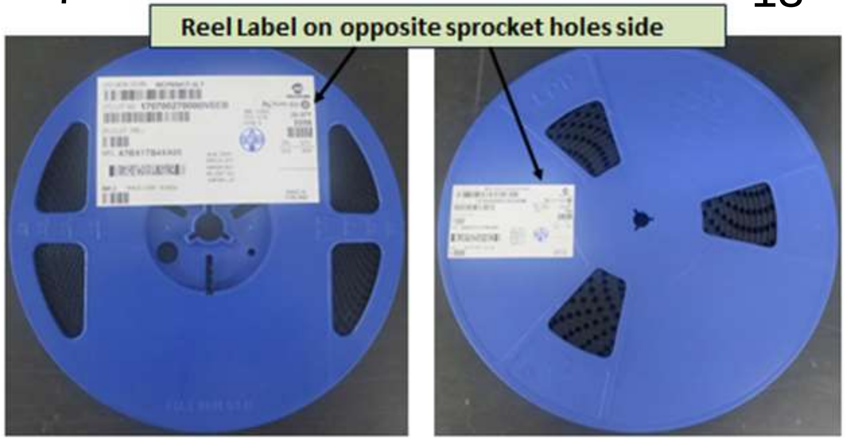
MRC 13"



POST CHANGE

7"

13"



Remove ESD label on reel

Packing method
SNR, PM

PRE CHANGE

- Use the kraft to fill in outer carton

UNIC

POST CHANGE

- Use bubble sheet to fill in outer carton

Packing material change
SNR, PM

PRE CHANGE

UNIC (MBB no Desiccant)

UTAC-TH (SSB+Desiccant)

UNIS (SSB+ Desiccant)

POST CHANGE

Part no.	Dimension W x L (cm)
24000023	37.0x42.0

Change bag for MSL1 product to Static Shield Bag (SSB)TnR without Desiccant and HIC

MSL1 caution label
SNR, PM

PRE CHANGE

UNIC

LEVEL

Caution

This bag contains

MOISTURE-SENSITIVE DEVICES

1

If blank , see adjacent bar code label

1. Calculated shelf life in sealed bag: 24 months at <40℃ and <90% relative humidity (RH)
2. Peak package body temperature: 260 ℃
   If blank , see adjacent bar code label
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must
   a) Mounted within Unlimited year of factory conditions
   If blank , see adjacent bar code label
   <30°C/60%RH, OR
   b) Stored at <10%RH
4. Devices require bake, before mountion, if:
   a) Humidity Indicator Card is >10% for level 2a-5a devices or >60% for level 2 devices when read at 23±5℃
   b) 3a or 3b not met
5. If baking is required reference IPC/JEDEC J-STD-033 for bake procedure
   reference IPC/JEDEC J-STD-033 for bake procedure

Bag Sealed Date : ____________

If blank , see adjacent bar code label

Note: Level and body temperature defined by IPC/JEDEC J-STD-020

For WLCSP

POST CHANGE

Remove MSL1 Label on MBB

Desiccant – Amount SNR, PM

PRE CHANGE

Subcon	Packing Media	Amount of Desiccant per one MBB
MRC San Jose	TnR	2 Units (2 units x 1 pouch)
UNIS	TnR	1 Unit (1 unit X 1 pouch)

MRC San Jose

UNIS

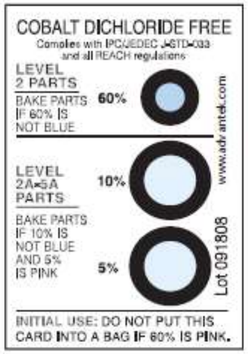
POST CHANGE

Packing Media	Amount of Desiccant per one MBB
TnR	2 Units (1 unit X 2 pouches)

Humidity Indicator Cards (HIC) SNR, PM

PRE CHANGE

MRC SAN JOSE



UNIS

Subcon	HIC Type
MRC San Jose	• 3 Dots (5%, 10%, 60%) • Cobalt Dichloride free
UNIS	• 3 Dots (5%, 10%, 60%) • Cobalt Dichloride free

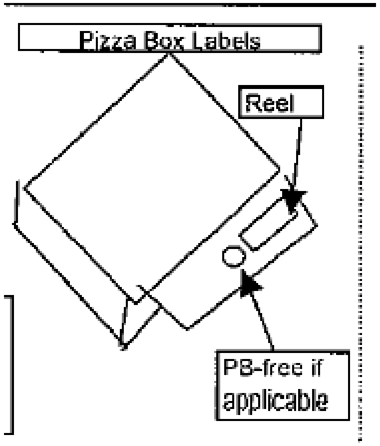
POST CHANGE

- 3 Dots (5%, 10%, 60%)
- Cobalt free

Moisture Sensitivity Identification label SNR, PM

PRE CHANGE

MRC San Jose



UNIS

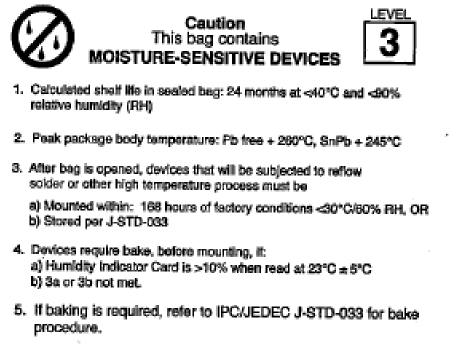
POST CHANGE

Add MSID label to affix on inner carton for moisture sensitive device

MSL Caution Label
SNR, PM

PRE CHANGE

MRC SAN JOSE



Caution
This bag contains
MOISTURE-SENSITIVE DEVICES

LEVEL
3

1. Calculated shelf life in sealed bag: 24 months at <40°C and <90% relative humidity (RH)
2. Peak package body temperature: Pb free + 260°C, SnPb + 245°C
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be
   a) Mounted within: 168 hours of factory conditions <30°C/60% RH, OR
   b) Stored per J-STD-033
4. Devices require bake, before mounting, if:
   a) Humidity Indicator Card is >10% when read at 23°C ± 5°C
   b) 3a or 3b not met.
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure.

Bag Seal Date: ______________________

Note: Level and body temperature defined by IPC/JEDEC J-STD-020

UNIS

CAUTION
THIS BAG CONTAINS
MOISTURE SENSITIVE DEVICES
DO NOT OPEN EXCEPT UNDER CONTROLLED CONDITIONS

LEVEL
3

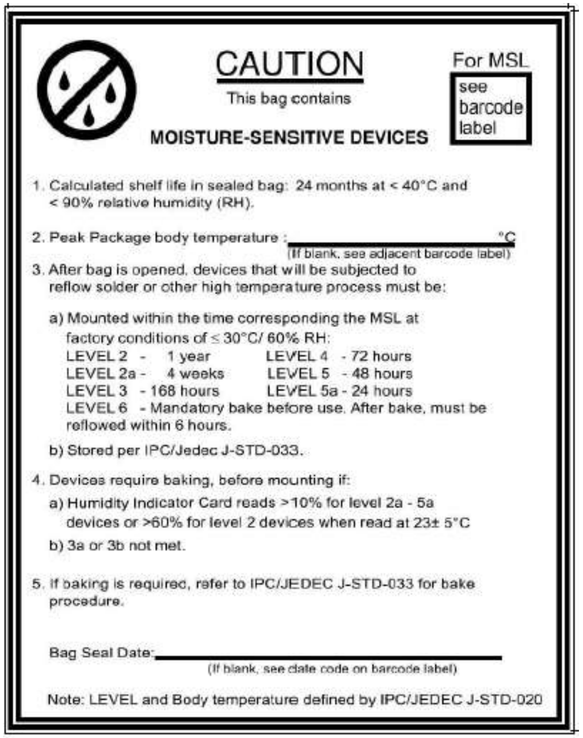
1. CALCULATED SHELF LIFE IN SEALED BAG:
   12 MONTHS AT < 40°C AND < 90% R.H. (relative humidity)
2. PEAK BODY TEMPERATURE: 260°C
3. AFTER BAG IS OPENED:
   DEVICES THAT WILL BE SUBJECTED TO REFLOW SOLDER OR OTHER HIGH TEMPERATURE PROCESS MUST BE:
   a) MOUNTED ON A BOARD WITHIN 168 HOURS OF OPENING AT FACTORY CONDITIONS AT OR BELOW 30°C / 60% R.H.
   b) OR STORED AT < 10% R.H.
4. **DEVICES REQUIRE BAKE, BEFORE MOUNTING, IF:**
   a) HUMIDITY INDICATOR CARD > 10% R.H. AT 23± 5°C
   b) 3a OR 3b IS NOT MET
5. IF BAKING IS REQUIRED:
   DEVICE MAY BE BAKED FOR 48 HOURS AT 125 ± 5°C
   NOTE: REFERENCE IPC / JEDEC J-STD-033 FOR OTHER BAKE OPTIONS

FOR BAG SEAL DATE: Jun 03 2019

NOTE: LEVEL & BODY TEMPERATURE DEFINED BY IPC / JEDEC J-STD-020

POST CHANGE

Change MSL caution and pre-print on MBB



CAUTION
This bag contains
MOISTURE-SENSITIVE DEVICES

For MSL
see barcode label

1. Calculated shelf life in sealed bag: 24 months at < 40°C and < 90% relative humidity (RH).
2. Peak Package body temperature : ____________ °C
   (If blank, see adjacent barcode label)
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be:
   a) Mounted within the time corresponding the MSL at factory conditions of ≤ 30°C/ 60% RH:
      LEVEL 2 - 1 year
      LEVEL 2a - 4 weeks
      LEVEL 3 - 168 hours
      LEVEL 4 - 72 hours
      LEVEL 5 - 48 hours
      LEVEL 5a - 24 hours
      LEVEL 6 - Mandatory bake before use. After bake, must be reflowed within 6 hours.
   b) Stored per IPC/Jedec J-STD-033.
4. Devices require baking, before mounting if:
   a) Humidity Indicator Card reads >10% for level 2a - 5a devices or >60% for level 2 devices when read at 23± 5°C
   b) 3a or 3b not met.
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure.

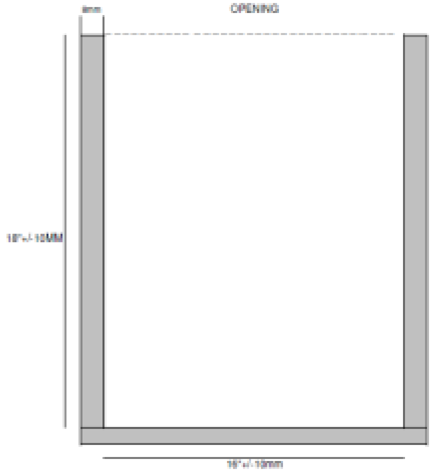
Bag Seal Date: ______________________
(If blank, see date code on barcode label)

Note: LEVEL and Body temperature defined by IPC/JEDEC J-STD-020

Moisture Barrier Bag (MBB)-13”TnR SNR, PM

PRE CHANGE

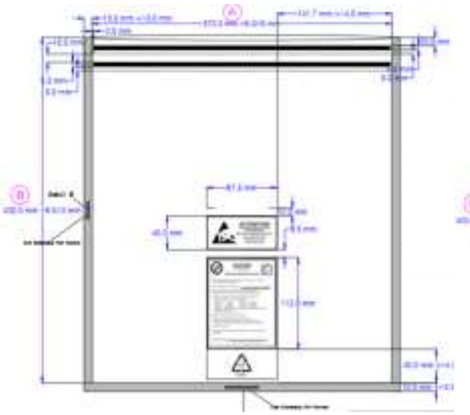
Subon	**Dimension W x L (cm)**
UNIS	40.6x45.7
MRC	43.1x48.2



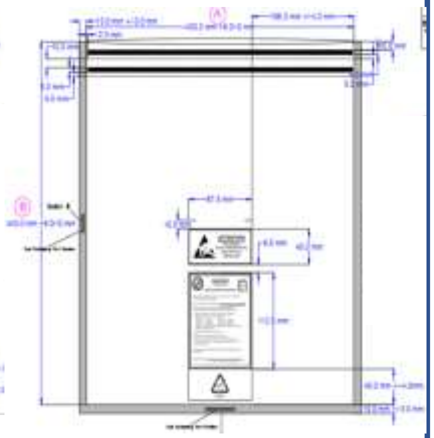
UNIS

POST CHANGE

Part no.	**Dimension W x L (cm)**
24000001 (Small)	37.0 x 42.0
24000006 (Large)	40.0 x 44.0



24000001 (Small)



24000006 (Large)

7” TnR Inner Carton
SNR, PM

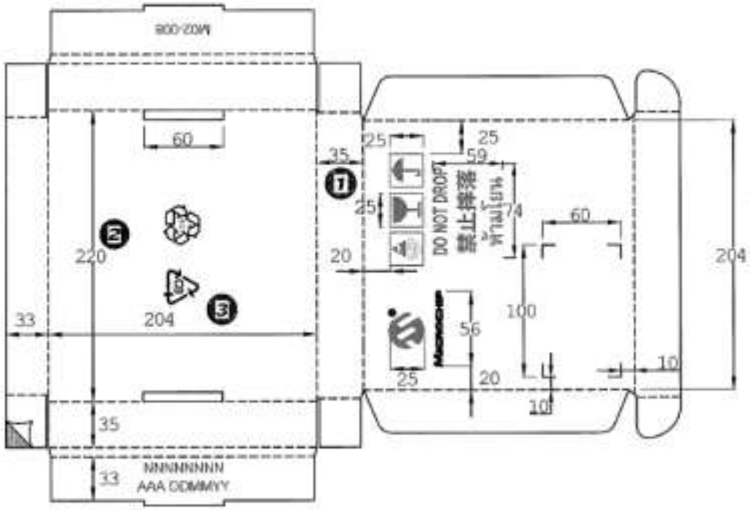
PRE CHANGE

BU	Subon	Dimension W x L x H (cm)
SNR, PM	UNIC (WLCSP)	19.5x21.0x3.9
	UTAC-TH	20.3x20.3x3.3
	UTAC-CH	20 x 20 x 7.5
	MRC San Jose	19.4x19.7x5.1

Refer Drawing in next page

POST CHANGE

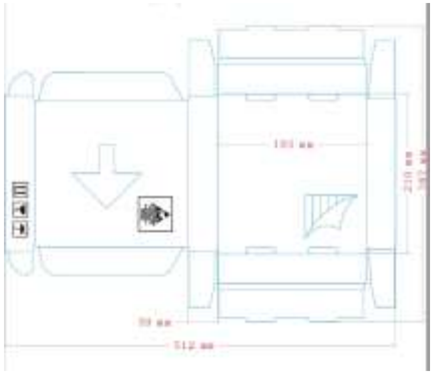
Drawing number	Dimension W x L x H (cm)
M02-008	22x20.4x3.3



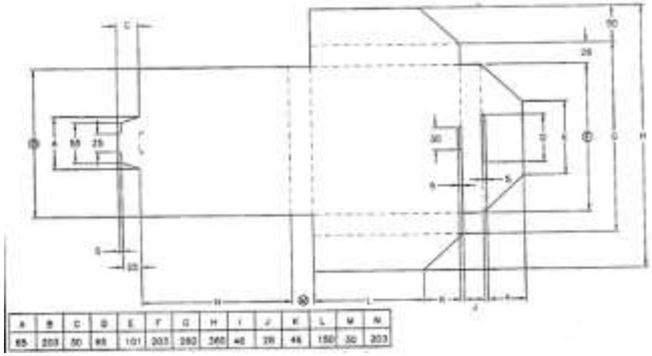
7” TnR Inner Carton
SNR, PM

PRE-CHANGE

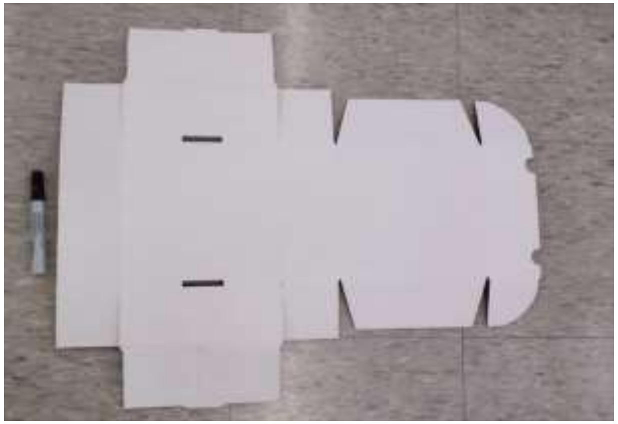
UNIC



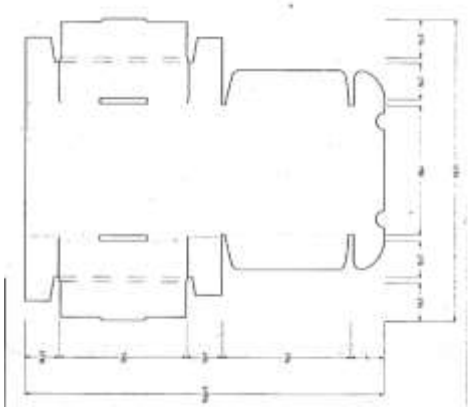
UTAC-TH



UTAC-CH



MRC



13” TnR Inner Carton
SNR, PM

PRE CHANGE

BU	**Subon**	**Dimension W x L x H (cm)**
SNR, PM	UNIC	34.7×35.2×5.3
	UNIS	35x35.2x5.1
	UTAC-TH	35.5x37.0x5.5
	UTAC-CH	35x37x8.0
	CIRTEK	34.3 x 37.0x 5.3
	MRC	34.3x 34.3x5.1
	SPEL	34.0 x 34.5 x 5.5

Refer Drawing in next page

POST CHANGE

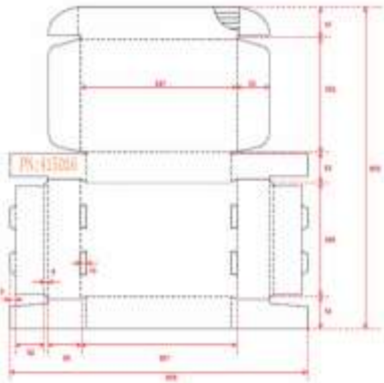
Drawing number	**Dimension W x L x H (cm)**
M02-009	34x35.6x5.0
M02-015 (Small)	37x35.1x5.3
M02-016 (Large)	37x35.3x7.7

Refer Drawing in next page

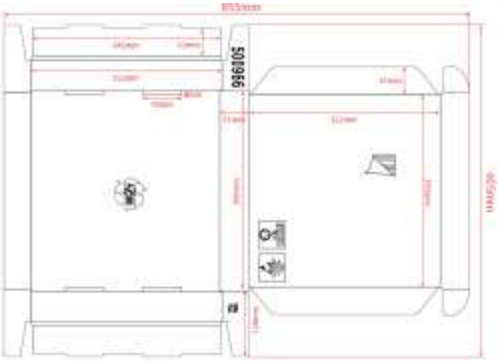
13” TnR Inner Carton SNR, PM

PRE-CHANGE

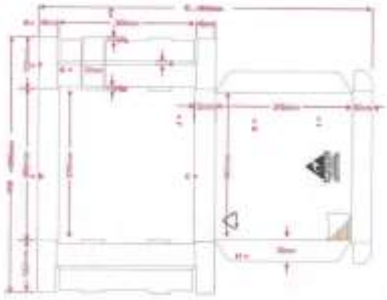
UNIC



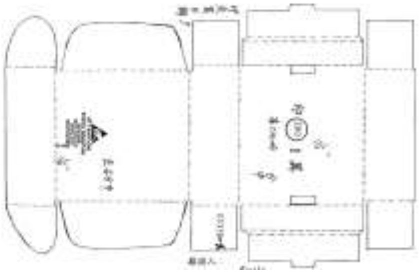
UNIS



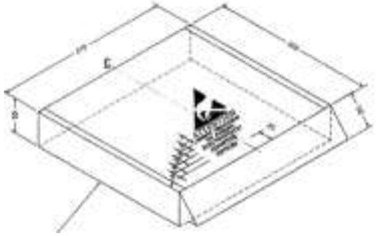
CIRTEK



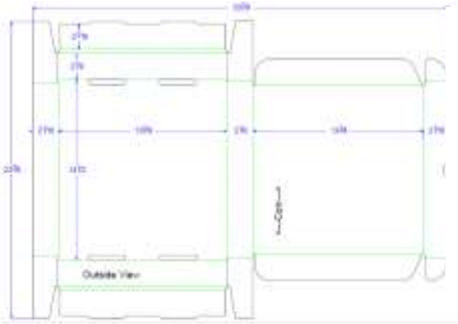
UTAC-CH



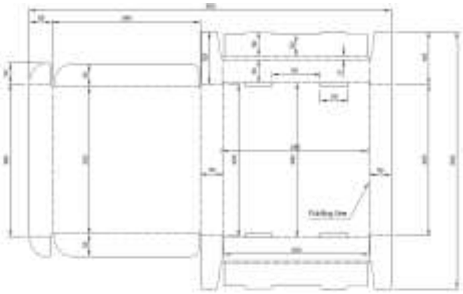
UTAC-TH



MRC



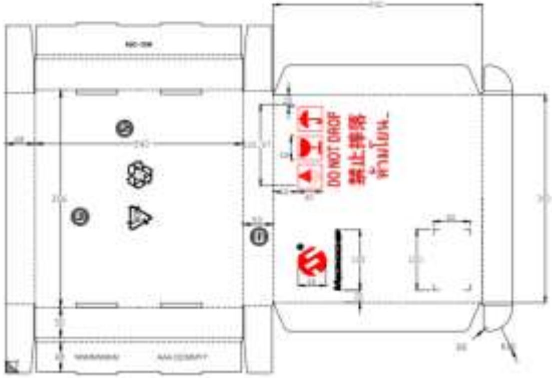
SPEL



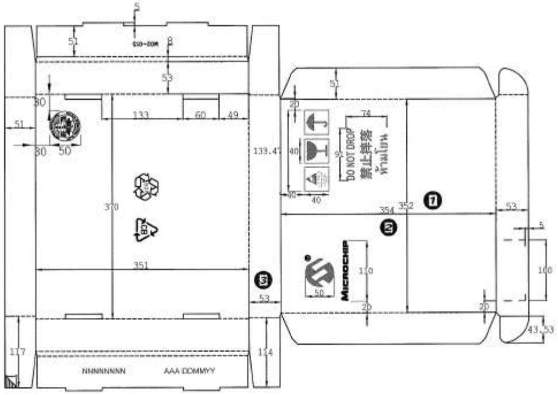
13” TnR Inner Carton
SNR, PM

POST CHANGE

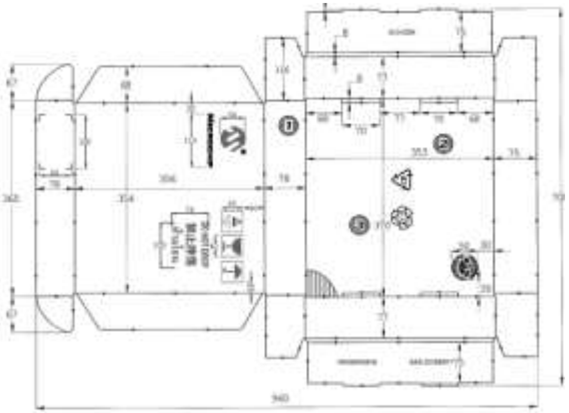
M02-009



M02-015 (Small)



M02-016 (Large)



Tube Inner Carton
SNR, PM

PRE CHANGE

Subcon	Dimension W x L x H (cm)
MSCC SAN JOSE	No Standard Tube Inner Carton

POST CHANGE

Drawing number	Dimension W x L x H (cm)
M02-009	34x35.6x5.0

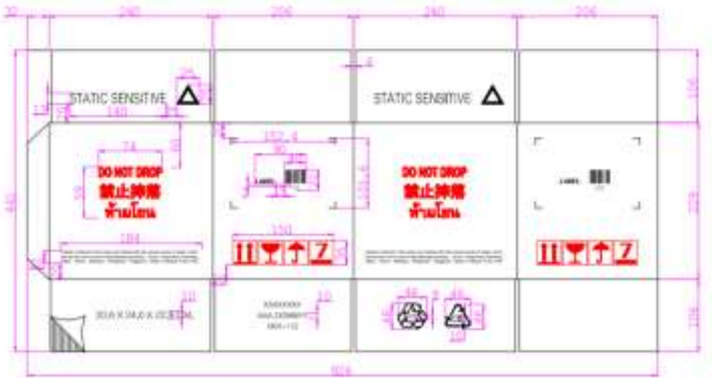
7” TnR Outer Carton SNR, PM

PRE CHANGE

Subcon	Dimension W x L x H (cm)	Inner : Outer
UNIC	22.7x36.7x22.5	8:1
	41x44x22.5	18:1
UTAC-TH	38.5x 38x15.5	4:1
	38.5x38x38.5	30:1
	66x39x39	60:1
UTAC-CH	50x317.5x34	12:1

POST CHANGE

Drawing No	Dimension W x L x H (cm)	Inner : Outer
M01-044 (SM)	37.0x38.0x11.0	2 : 1
M01-112 (LO)	20.6x24.0x22.9	5 : 1
M01-038 (RT)	20x46x23	10 : 1



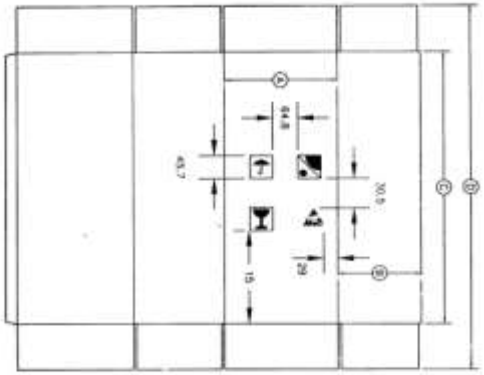
M01-112 (LO)	20.6x24.0x22.9	5 : 1

7” TnR Outer Carton
SNR, PM

PRE-CHANGE

UNIC

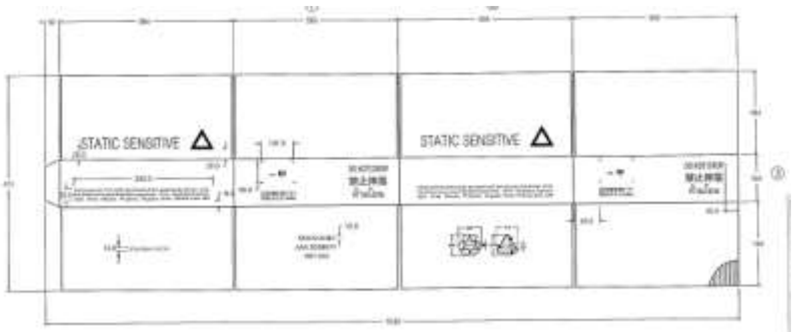
UTAC-TH



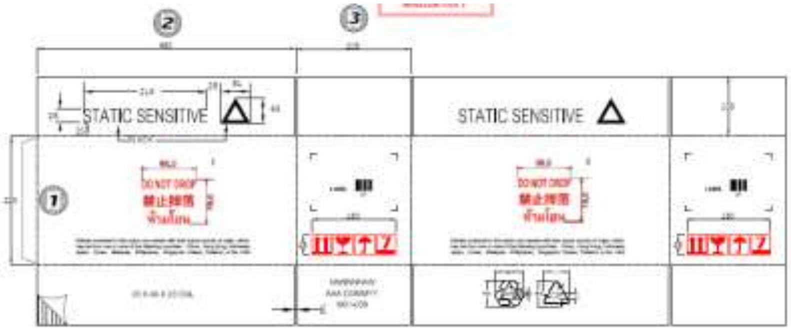
UTAC-CH

7” TnR Outer Carton
SNR, PM

POST CHANGE



M01-044 (SM)	37.0x38.0x11.0	2 : 1



M01-038 (RT)	20x46x23	10 : 1

13” TnR Outer Carton SNR, PM

PRE CHANGE

Subcon	Dimension W x L x H (cm)	Inner : Outer
Garden Grove	38.1x38.1x10.16	1:1
	38.1x38.1x30.48	5:1
	38.1x38.1x38.1	6:1
	38.1x38.1x60.96	10:1
USIC	39x60x39	10:1
	30x38.5x38.5	5:1
	38.5x38.5x19.0	3:1
UNIS	38x38.5x12.5	2:1
	39x39x40	6:1
	40x59x38.5	10:1
	36x62x52.5	12:1
UTAC-TH	38.5x 38x15.5	2:1
	38.5x38x38.5	5:1
	66x39x39.0	11:1
UTAC-CH	37.8x34x36.8	4:1

POST CHANGE

Drawing No	Dimension W x L x H (cm)	Inner : Outer	
		M02-009 M02-015	M02-016
M01-044 (SM)	37.0x38.0x11.0	1 : 1	1 : 1
M01-045 (S4)	37.0x38.0x22.5	3 : 1	2 : 1
M01-046 (S5)	37.0x39.0x39.0	6 : 1	4 : 1
M01-047 (S3)	42.0x66.0x39.0	11 : 1	8 : 1

Tube Outer Carton
SNR, PM

PRE CHANGE

Subcon	Dimension W x L x H (cm)	Inner : Outer
Garden Grove	38.1x38.1x10.16	1:1

POST CHANGE

Drawing No	Dimension W x L x H (cm)	Inner : Outer
M01-022 (PP)	15.5x62.0x14.0	1 : 1
M01-028 (C4)	28x63.5x11	2 : 1
M01-029 (C6)	28x63.5x15.5	3 : 1
M01-030 (C8)	28x63.5x20	4 : 1

Label and Packing material change of PoE-IC

Part Aging
PoE-IC

PRE CHANGE

Microsemi may ship parts up to 24 months (2 years). Parts older than 24 months (2 years) will shipped only after prior approval from

POST CHANGE

Microchip may ship parts up to 48 months (4 years). Parts older than 24 months (2 years) old will be recertified prior to shipment. The requirement will be applied for both automotive and commercial.

Reason: Material sets used to manufacture integrated circuits have shown no degradation in solderability, moisture sensitivity or reliability of products after 48 months.

For more information related to Microchip's part aging strategy, please visit the following link on our website: Component Age Policy

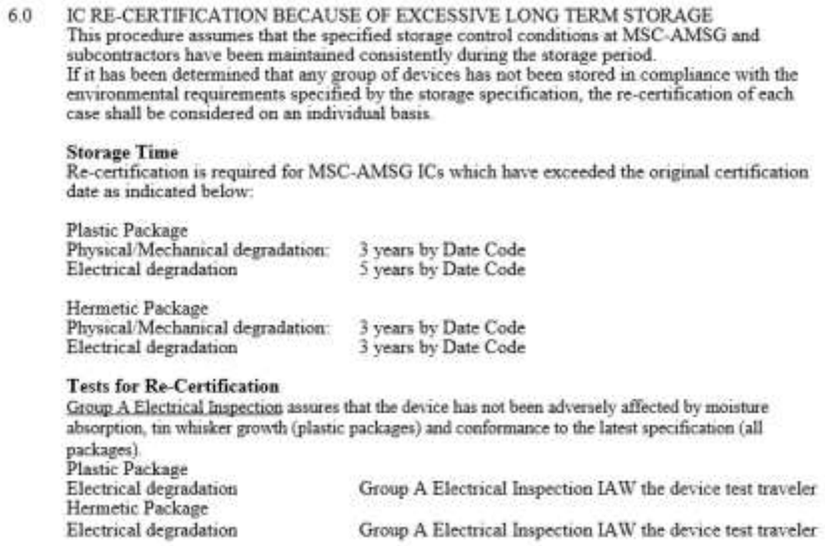
Combination Rule
PoE-IC

PRE CHANGE	POST CHANGE
•1 Device. **•2 Date codes.** •No limit to number of production lots follow date code combination rule. •1 Assembly Site. •1 Test Site. •1 Wire Material. •No limit for Die Revision, Die ID, Fab Revision, Different T/C, and test flow.	•1 Device. **•3 Date codes.** •No limit to number of production lots follow date code combination rule. •1 Assembly Site. •1 Test Site. •1 Wire Material. •No limit for Die Revision, Die ID, Fab Revision, Different T/C, and test flow.

Recertification Program
PoE-IC

PRE CHANGE

Recertification of solderability at 3 years and solderability and electrical test at 5 years.



6.0 IC RE-CERTIFICATION BECAUSE OF EXCESSIVE LONG TERM STORAGE
This procedure assumes that the specified storage control conditions at MSC-AMSG and subcontractors have been maintained consistently during the storage period.
If it has been determined that any group of devices has not been stored in compliance with the environmental requirements specified by the storage specification, the re-certification of each case shall be considered on an individual basis.

Storage Time
Re-certification is required for MSC-AMSG ICs which have exceeded the original certification date as indicated below:

Plastic Package	
Physical/Mechanical degradation:	3 years by Date Code
Electrical degradation	5 years by Date Code

Hermetic Package	
Physical/Mechanical degradation:	3 years by Date Code
Electrical degradation	3 years by Date Code

Tests for Re-Certification
Group A Electrical Inspection assures that the device has not been adversely affected by moisture absorption, tin whisker growth (plastic packages) and conformance to the latest specification (all packages).

Plastic Package	
Electrical degradation	Group A Electrical Inspection IAW the device test traveler
Hermetic Package	
Electrical degradation	Group A Electrical Inspection IAW the device test traveler

POST CHANGE

Parts older than 24 months (2 years) old will be recertified prior shipment. It may include one or more of the following: inspections, retest, rescanning and repacking of parts.

WIP: Original datecode exceeds 22 months and it is not over 3 years 10 months.

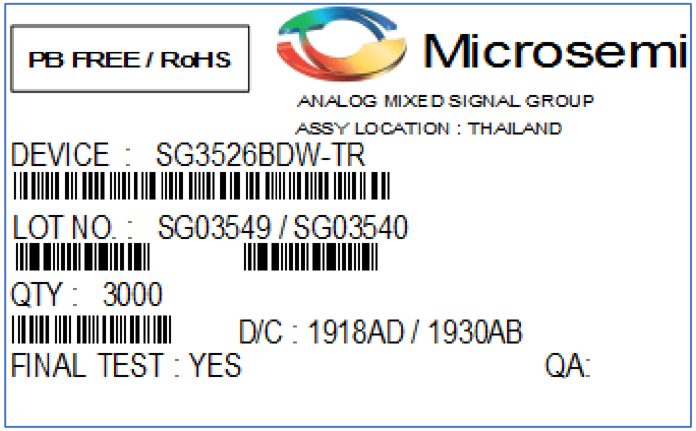
FG : Original datecode exceeds 23 months and it is not over 4 years.

RMA : Original datecode exceeds 24 months and and it is not over 4 years.

Reel/Bag/Inner Label
PoE - IC

PRE-CHANGE

ASEM



PB FREE / RoHS

Microsemi

ANALOG MIXED SIGNAL GROUP

ASSY LOCATION : THAILAND

DEVICE : SG3526BDW-TR

LOT NO. : SG03549 / SG03540

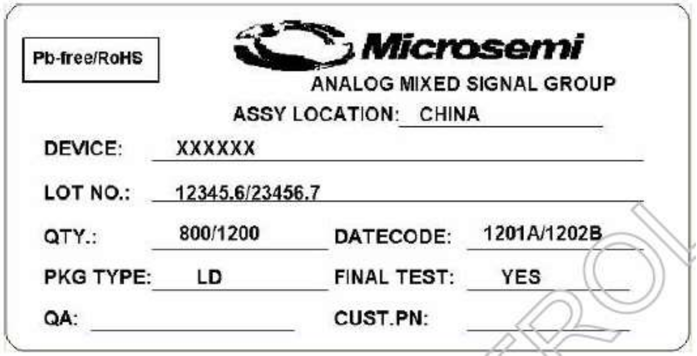
QTY : 3000

D/C : 1918AD / 1930AB

FINAL TEST : YES

QA:

UNISEM CHINA



Pb-free/RoHS

Microsemi

ANALOG MIXED SIGNAL GROUP

ASSY LOCATION: CHINA

DEVICE: XXXXXX

LOT NO.: 12345.6/23456.7

QTY.: 800/1200

DATECODE: 1201A/1202B

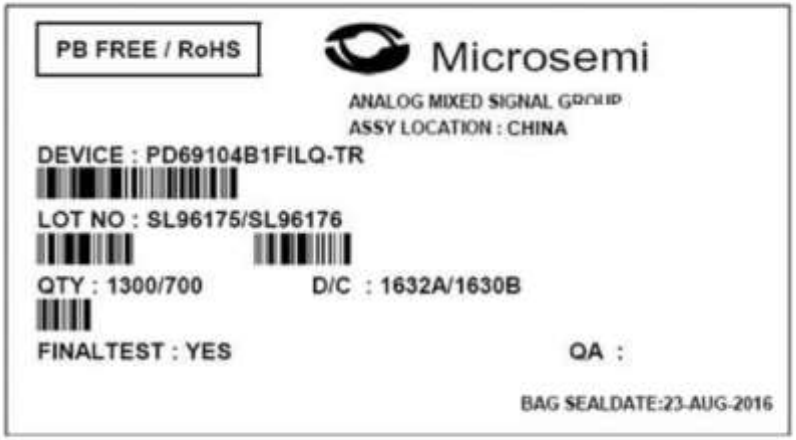
PKG TYPE: LD

FINAL TEST: YES

QA:

CUST.PN:

UTAC THAILAND



PB FREE / RoHS

Microsemi

ANALOG MIXED SIGNAL GROUP

ASSY LOCATION : CHINA

DEVICE : PD69104B1FILQ-TR

LOT NO : SL96175/SL96176

QTY : 1300/700

D/C : 1632A/1630B

FINALTEST : YES

QA :

BAG SEALDATE:23-AUG-2016

Reel/Bag/Inner Label
PoE-IC

POST CHANGE

(1P) CATALOG P/N: **ABCDEFGKIJKL-BB-CC-DDDD-EEEEE-FF**

(1T) LOT NO.: **114601899000MTAI**

Pb RoHS e3

MSL: 3/260 C
PKG: TFBGA
LEAD: 48

(Q) QTY
2500

(P) CUST. P/N: **ABCDEFGH IJKLMNO PQRSTUV REV A**

D/C	QTY
1407	250
1408	1000
1509	1250

MPC: **ABCDEFGHKLMNO**

SEAL DATE: MM/DD/YY
WAFER QTY: -
WAFER REV: -
RECERT D/C: -
WAFER LOT: -

ID#:(001) TRACE CODE: 1407B1R,1408B1Q,1509A3R

MADE IN
THAILAND

Reel/Bag/Inner Label PoE-IC

PRE CHANGE			POST CHANGE		
Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode
Pb-Free/RoHS Symbol	Yes	No	Pb Free Symbol	Yes	No
			RoHS Symbol	Yes	No
Microsemi logo	Yes	No	Microchip logo	Yes	No
Assy Location	Yes	No	-	-	-
DEVICE	Yes	Yes	(1P) CATALOG P/N	Yes	Yes
LOT No	Yes	Yes	(1T) LOT NO	Yes	Yes
QTY BOX	Yes	Yes	(Q) QTY	Yes	Yes
FINAL TEST	Yes	No	-	-	-
QA	Yes	No	-	-	-
-	-	-	ID#	Yes	Yes
-	-	-	MPC	Yes	No

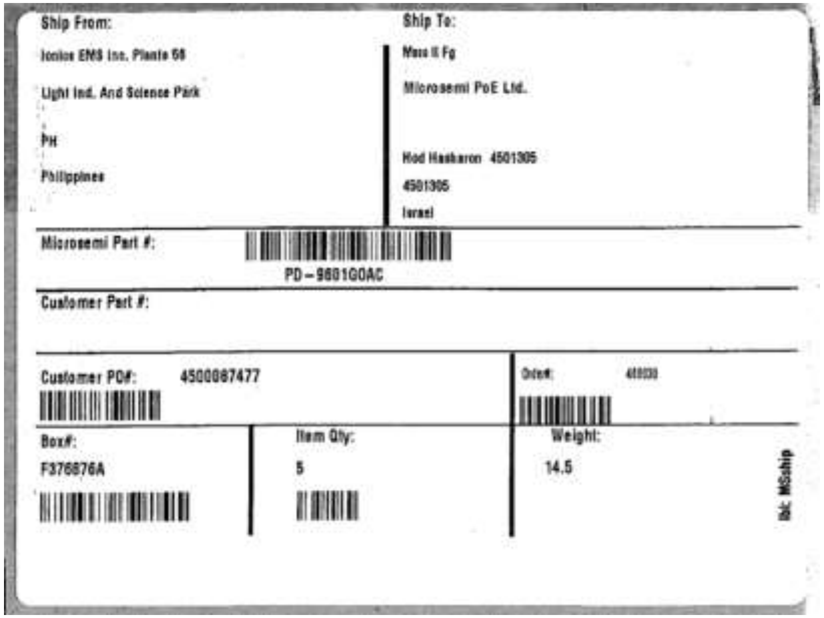
Reel/Bag/Inner Label
PoE-IC

POST CHANGE			POST CHANGE		
Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode
-	-	-	D/C	Yes	No
-	-	-	(QTY)	Yes	No
-	-	-	MADE IN	Yes	No
-	-	-	eCAT Symbol	Yes	No
-	-	-	(P) CUST. P/N	Yes	Yes
-	-	-	MSL	Yes	No
-	-	-	SEAL DATE	Yes	No
-	-	-	TRACE CODE	Yes	No
-	-	-	China RoHS Symbol	Yes	No
-	-	-	PKG	Yes	No
-	-	-	LEAD	Yes	No
-	-	-	WAFER QTY	Yes	No
-	-	-	WAFER REV	Yes	No
-	-	-	RECERT D/C	Yes	No

Outer Label
PoE-IC

PRE CHANGE

XPO-HK



Ship From:
Ionics EMS Inc. Plants 58
Light Ind. And Science Park
PH
Philippines

Ship To:
Mass II Fg
Microsemi PoE Ltd.
Hod Hasharon 4501305
4501305
Israel

Microsemi Part #: PD-9601G0AC

Customer Part #:

Customer PO#: 4500087477

Order#: [illegible]

Box#: F376676A

Item Qty: 5

Weight: 14.5

lbl: MSship

POST CHANGE

B-HK-PHC-S2269812

SHIP TO: PHILIPS CONSUMER ELECTRONICS
WILSON LOGISTIC CT, 6/F
PHILIPS IND BLDG., 24-28 KUNG
KUNG YIP ST, KWAICHUNG
HONG KONG

Cust. P/N: 3139 227 01992

Catalog P/N: DSPIC33FJ128MC510T-I/PTC22

Pb e0 RoHS 50

PO#: 55016400/2

SO #: 472542/26

Qty: 200000

Hong Kong
10-21-2010
(mm-dd-yyyy)

Carton 1
of 20
19.5 kgs

Outer Label PoE-IC

PRE CHANGE			POST CHANGE		
Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode
SHIP FROM	Yes	No	-	-	-
SHIP TO	Yes	No	SHIP TO	Yes	No
Customer PO#	Yes	Yes	PO#	Yes	Yes
Customer Part#	Yes	Yes	Cust P/N	Yes	Yes
Microsemi Part#	Yes	Yes	Catalog P/N	Yes	Yes
Order#	Yes	Yes	SO#	Yes	Yes
	-	-	(mm-dd-yyyy)	Yes	No
BoX#	Yes	Yes	-	-	-
Item Qty	Yes	Yes	No of carton	Yes	No
-	-	-	eCAT Symbol	Yes	No
-	-	-	Pb Free Symbol	Yes	No
-	-	-	RoHS Symbol	Yes	No
-	-	-	China RoHS Symbol	Yes	No
-	-	-	Ship Number	Yes	Yes
-	-	-	2D barcode	No	Yes
Weight	-	-	Gross Weight	Yes	No

MSL3 Caution Label PoE-IC

PRE-CHANGE

ASEM

CAUTION

This Bag Contains
MOISTURE SENSITIVE DEVICES

LEVEL 3
If blank, see adjacent barcode label

1. Calculated shelf life in sealed bag: 12month at < 40 °C and < 90% relative humidity (RH)
2. a) Limited to peak package body temperature of 220°C if label indicates **SN/PB** ,OR
   b) Limited to peak package body temperature of 260°C if label indicates Pb , OR Pb **GREEN**
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must
   a) Mounted within: 168 hours of factory conditions < 30°C/60% RH, OR
   b) Stored at < 10%RH
4. Devices require bake, before mounting, if:
   a) Humidity Indicator Card is > 10% when read at 23 ± 5° C
   b) 3a or 3b not met
5. If baking is required, devices may be baked for 24 hours at 125 ± 5°C
   Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J – STD – 033 for bake procedure

Bag Seal Date: 26APR05
(If blank, see bar code label)

Note: Level and body temperature defined by IPC/JEDEC J – STD – 020

UTAC

Caution

This Bag Contains
MOISTURE-SENSITIVE DEVICES

LEVEL 3
If blank, see adjacent bar code label

1. Calculated shelf life in sealed bag : 12 months at < 40 °C and < 90% relative humidity (RH)
2. Peak package body temperature: 260 °C
   If blank, see adjacent bar code label
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be
   a) Mounted within: 168 hours of factory conditions
   If blank, see adjacent bar code label
   ≤ 30 °C / 60% RH, or
   b) Stored per J-STD-033
4. Devices require bake, before mounting, if:
   a) Humidity Indicator Card reads > 10% for level 2a-5a device or > 60% for level 2 devices when read at 23 ± 5 °C
   b) 3a or 3b are not met
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure

Bag Seal Date: May 08, 2017
If blank, see adjacent bar code label

Note: Level and body temperature defined by IPC/JEDEC J-STD-020

UNIC

CAUTION

This bag contains
MOISTURE SENSITIVE DEVICES

LEVEL 3

1. Calculated shelf life in sealed bag: 12 months at < 40°C and < 90% relative humidity (RH).
2. Peak package body temperature: 260 °C
   If blank, see adjacent bar code label
3. After this bag is opened, devices that will be subjected to reflow solder or other high temperature process must
   a) Mounted within: 168 hours of factory
   If blank, see adjacent bar code label
   conditions < 30°C/60%
   b) Stored at < 10% RH
4. Devices require bake, before mounting if:
   a) Humidity Indicator Card is > 10% when read at 23 +/- 5°C
   b) 3a or 3b not met.
5. If baking is required, devices may be baked for [illegible] hours at 125 +/- 5°C

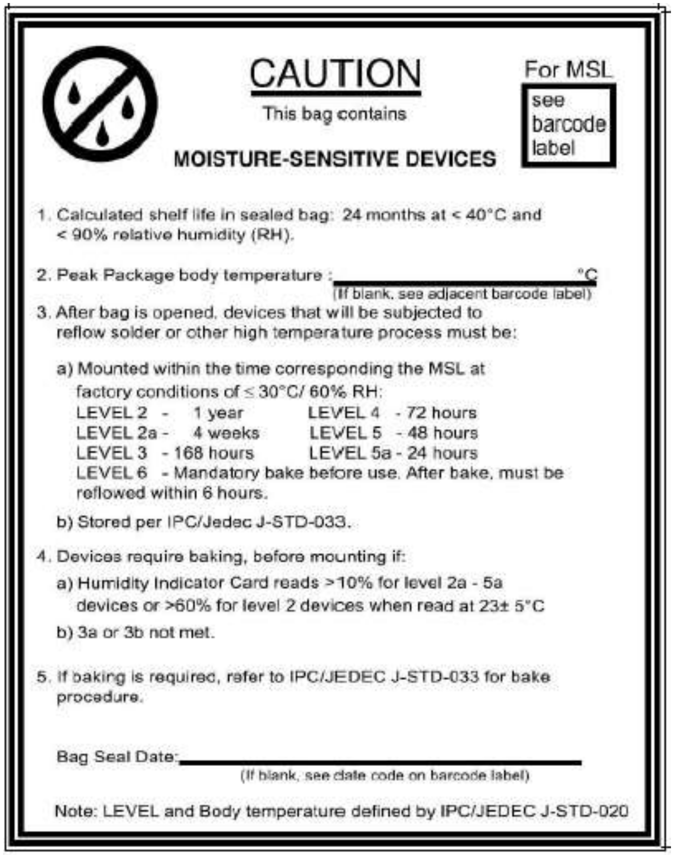
Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure.

Bag Seal Date:
(If blank, see bar code label)

Note: LEVEL defined by EIA JEDEC Standard JESD22- A112

MSL3 Caution Label
PoE-IC

POST CHANGE



CAUTION

This bag contains

MOISTURE-SENSITIVE DEVICES

For MSL

see
barcode
label

1. Calculated shelf life in sealed bag: 24 months at < 40°C and < 90% relative humidity (RH).

2. Peak Package body temperature : ____________ °C
(If blank, see adjacent barcode label)

3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be:

a) Mounted within the time corresponding the MSL at factory conditions of ≤ 30°C/ 60% RH:

LEVEL 2	- 1 year	LEVEL 4	- 72 hours
LEVEL 2a	- 4 weeks	LEVEL 5	- 48 hours
LEVEL 3	- 168 hours	LEVEL 5a	- 24 hours

LEVEL 6 - Mandatory bake before use. After bake, must be reflowed within 6 hours.

b) Stored per IPC/Jedec J-STD-033.

4. Devices require baking, before mounting if:

a) Humidity Indicator Card reads >10% for level 2a - 5a devices or >60% for level 2 devices when read at 23± 5°C

b) 3a or 3b not met.

5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure.

Bag Seal Date: ____________
(If blank, see date code on barcode label)

Note: LEVEL and Body temperature defined by IPC/JEDEC J-STD-020

- Change calculated shelf life from 12 months to 24 months
- Pre-print on MBB

Desiccant – Amount
PoE-IC

PRE CHANGE

Subcon	Packing Media	Amount of Desiccant per one MBB
ASEM	13” TnR	4 Units (2 units X 2 pouches)
UTAC	13” TnR	4 Units (2 units X 2 pouches)
UNIC	13” TnR	1 Unit (1 units x 1 pouch)

ASEM

UTAC-TH

UNIC

Compliant with Mil-D-3464, TYPEI and II

POST CHANGE

Packing Media	Amount of Desiccant per one MBB
13” TnR	2 Units (1 unit X 2 pouches)

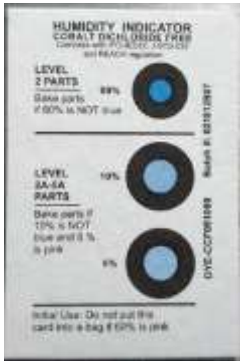
Compliant with Mil-D-3464, TYPEI and II

Humidity Indicator Cards (HIC)
PoE-IC

PRE CHANGE

ASEM

UTAC



UNIC

Subcon	HIC Type
ASEM	• 3 Dots (5%, 10%, 60%) • Cobalt Dichloride free
UTAC	• 3 Dots (5%, 10%, 60%) • Cobalt Dichloride free
UNIC	• 6 Dots (10%, 20%, 30%, 40%, 50%, 60%) • Cobalt free

POST CHANGE

- 3 Dots (5%, 10%, 60%)
- Cobalt free

ESD Label on Reel
PoE-IC

PRE CHANGE

ESD label affix on reel

ESD Symbol mark on reel

POST CHANGE

Remove ESD label affix on reel

Moisture Barrier Bag (MBB)-13"TnR PoE-IC

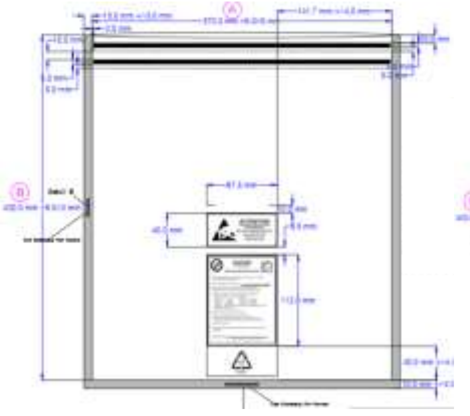
PRE CHANGE

Packing media	Subon	Dimension W x L (cm)
13" TnR	ASEM	40.64 x 45.72
	UTAC	37.60 x 44.45
	UNIC	40.64 x 45.72

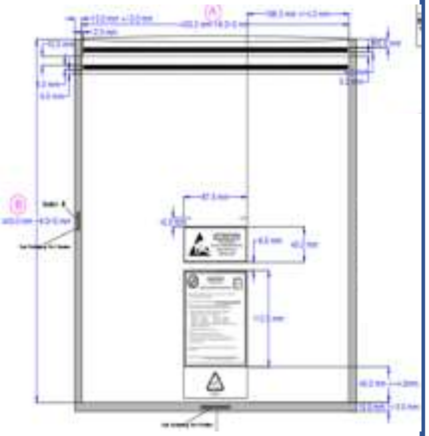
Refer drawing next page

POST CHANGE

Part no.	Dimension W x L (cm)
24000001 (Small)	37.0 x 42.0
24000006 (Large)	40.0 x 44.0



24000001 (Small)



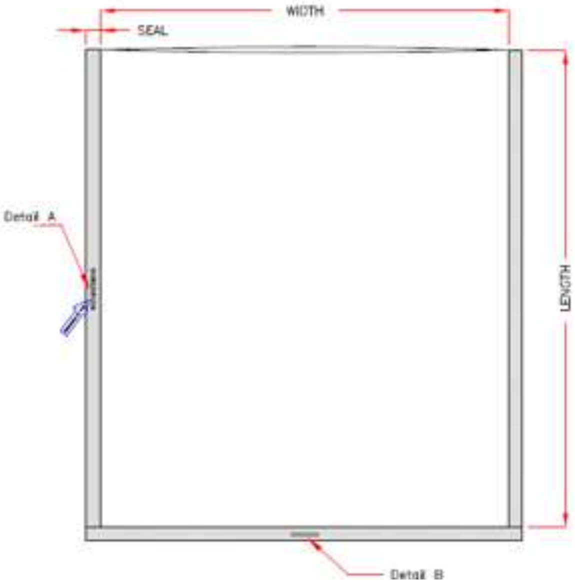
24000006 (Large)

Moisture Barrier Bag (MBB)-13"TnR PoE-IC

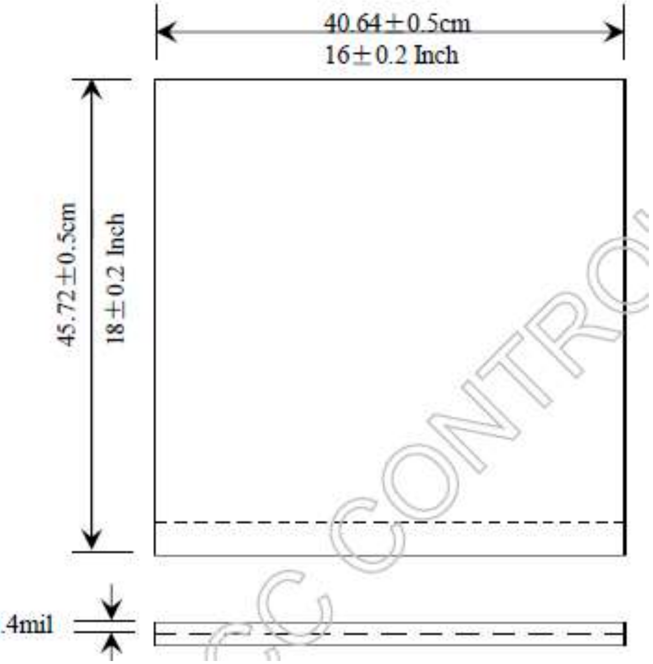
PRE-CHANGE

ASEM

UTAC



UNIC



6±0.4mil

Moisture Sensitivity Identification label (MSID Label) PoE-IC

PRE CHANGE

ASEM

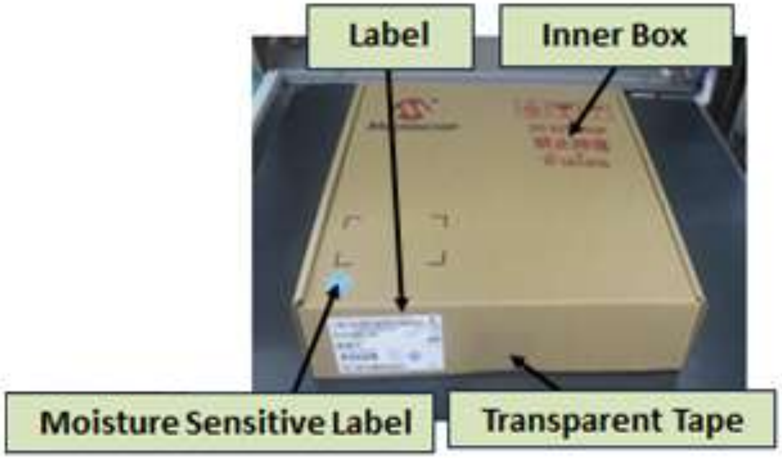
UTAC

UNIC

No MSID label on inner carton

POST CHANGE

Add MSID label to affix on inner carton for moisture sensitive device



13” TnR Inner Carton
PoE-IC

PRE CHANGE

Subcon	**Drawing number**	**Dimension W x L x H (cm)**
ASEM	115002522	34X34X7.0
UTAC	26030014	35.5X37.0X5.5
UNIC	510010	33.8x35.5x4.1

Refer Drawing in next page

POST CHANGE

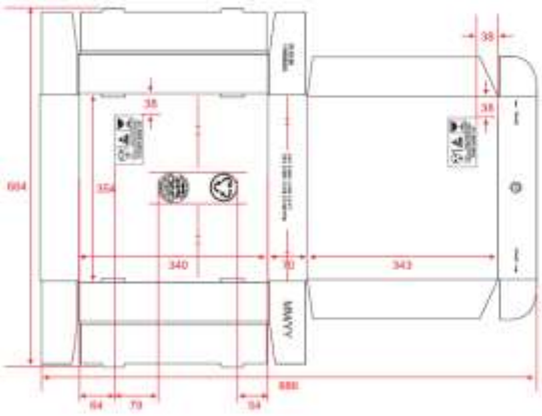
Drawing number	**Dimension W x L x H (cm)**
M02-009 For UTAC, UNIC	34x35.6x5.0
M02-015 (Small) For ASEM	37x35.1x5.3
M02-016 (Large) For ASEM	37x35.3x7.7

Refer Drawing in next page

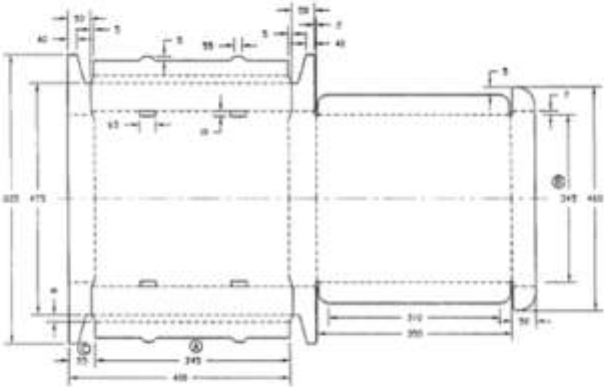
13" TnR Inner Carton PoE-IC

PRE-CHANGE

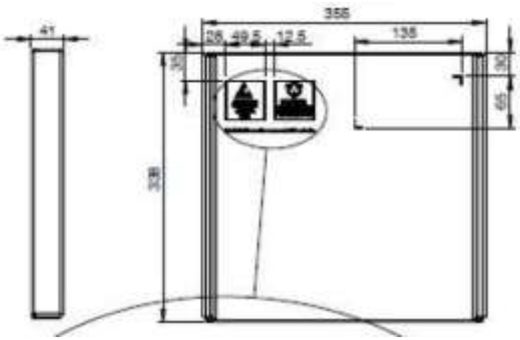
ASEM



UTAC



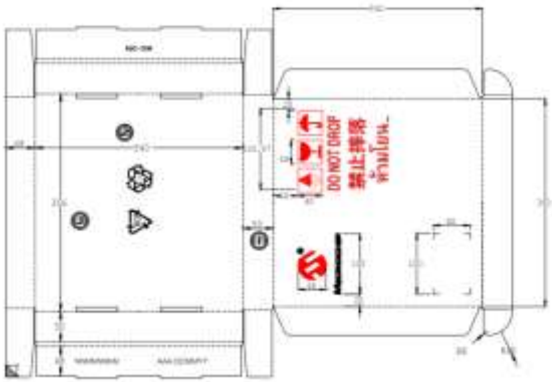
UNIC



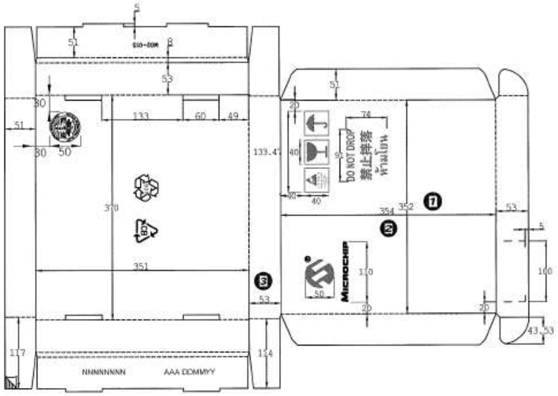
13” TnR Inner Carton
PoE-IC

POST CHANGE

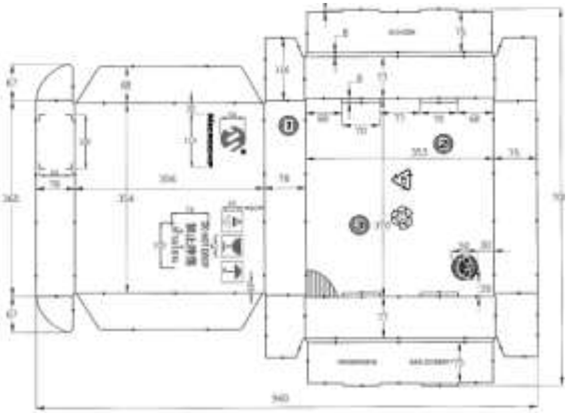
M02-009



M02-015 (Small)



M02-016 (Large)



13” TnR Outer Carton
PoE-IC

PRE CHANGE

Warehouse	Dimension W x L x H (cm)	Inner : Outer
XPO-HK	10x38 x38	1 : 1
	21x39x39	4 : 1
	33x39x39	7 : 1

POST CHANGE

Drawing No	Dimension W x L x H (cm)	Inner : Outer	
		M02-009 M02-015	M02-016
M01-044 (SM)	37.0x38.0x11.0	1 : 1	1 : 1
M01-045 (S4)	37.0x38.0x22.5	3 : 1	2 : 1
M01-046 (S5)	37.0x39.0x39.0	6 : 1	4 : 1
M01-047 (S3)	42.0x66.0x39.0	11 : 1	8 : 1

Label and Packing material change of PoE-MCU

(Buy & Resale)

Part Aging
PoE-MCU (Buy & Resale)

PRE CHANGE	POST CHANGE
Microsemi may ship parts up to 24 months (2 years). Parts older than 24 months (2 years) will shipped only after prior approval from the customer.	Microchip may ship parts up to 48 months (4 years). Parts older than 24 months (2 years) old will be recertified prior to shipment. The requirement will be applied for both automotive and commercial. Reason: Material sets used to manufacture integrated circuits have shown no degradation in solderability, moisture sensitivity or reliability of products after 48 months. *For more information related to Microchip's part aging strategy, please visit the following link on our website: Component Age Policy*

Combination Rule
PoE-MCU (Buy & Resale)

PRE CHANGE

- 1 Device.
- **2 Date codes.**
- No limit to number of production lots follow date code combination rule.
- 1 Assembly Site.
- 1 Test Site.
- 1 Wire Material.
- No limit for Die Revision, Die ID, Fab Revision, Different T/C, and test flow.

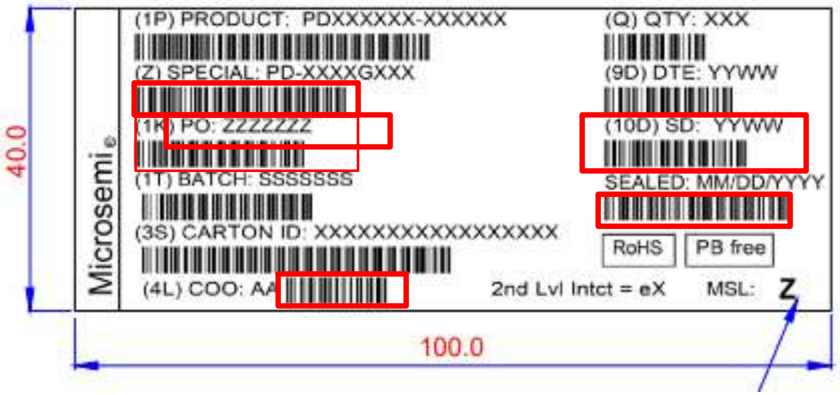
POST CHANGE

- 1 Device.
- **3 Date codes.**
- No limit to number of production lots follow date code combination rule.
- 1 Assembly Site.
- 1 Test Site.
- 1 Wire Material.
- No limit for Die Revision, Die ID, Fab Revision, Different T/C, and test flow.

Inner Label
PoE-MCU (Buy & Resale)

PRE CHANGE

Same label as MBB label



Microsemi®

(1P) PRODUCT: PDXXXXXX-XXXXXX
(Q) QTY: XXX
(Z) SPECIAL: PD-XXXXGXXX
(9D) DTE: YYWW
(1K) PO: ZZZZZZZ
(10D) SD: YYWW
(1T) BATCH: SSSSSSS
SEALED: MM/DD/YYYY
(3S) CARTON ID: XXXXXXXXXXXXXXXXX
RoHS
PB free
(4L) COO: AA
2nd Lvl Intct = eX
MSL: Z

LPN

Microsemi®

(1P) PRODUCT PD69200C-016721-TR
(Q) QTY 979
(Z) SPECIAL PD-0821GR03
(9D) DTE 18351836
(1K) PO 5500095346
(10D) SD 1903
(1T) BATCH 714524-1
SEALED 01/14/19
(3S) CARTON ID PMC07145240101404708
RoHS
PB free
(4L) COO CN
2nd Lvl Inct = e3
MSL3

POST CHANGE

(1P) CATALOG P/N: **ABCDEFGKIJKL-BB-CC-DDDD-EEEEE-FF**

(1T) LOT NO.: **114601899000MTAI**

Pb RoHS e3

MSL: 3/260 C
PKG: TFBGA
LEAD: 48

(Q) QTY
2500

(P) CUST. P/N: **ABCDEFGH IJKLMNO PQRSTUV REV A**

MPC: **ABCDEFGHKLMNO**

SEAL DATE: MM/DD/YY
WAFER QTY: -
WAFER REV: -
RECERT D/C: -
WAFER LOT: -

D/C	QTY
1407	250
1408	1000
1509	1250

ID#:(001) TRACE CODE: 1407B1R,1408B1Q,1509A3R

MADE IN THAILAND

No barcode for MPC
SD: No Programing D/C*
No PO
No barcode for Seal date
No barcode for COO

Inner Label
PoE-MCU (Buy & Resale)

PRE CHANGE			POST CHANGE		
Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode
(1P) PRODUCT	Yes	Yes	(1P) CATALOG P/N	Yes	Yes
(Z) SPECIAL	Yes	Yes	MPC	Yes	No
(1T) BATCH	Yes	Yes	(1T) LOT NO	Yes	Yes
(9D) DTE	Yes	Yes	D/C	Yes	No
			QTY per D/C	Yes	No
(Q) QTY	Yes	Yes	(Q) QTY	Yes	Yes
COO	Yes	Yes	MADE IN	Yes	No
(3S) CARTON ID	Yes	Yes	-	-	-
Pb Free	Yes	No	Pb Free Symbol	Yes	No
(10D) SD	Yes	Yes	-	-	-
PO	Yes	Yes	-	-	-
-	-	-	eCAT Symbol	Yes	No
-	-	-	(P) CUST. P/N	Yes	Yes

* SD: Programming date

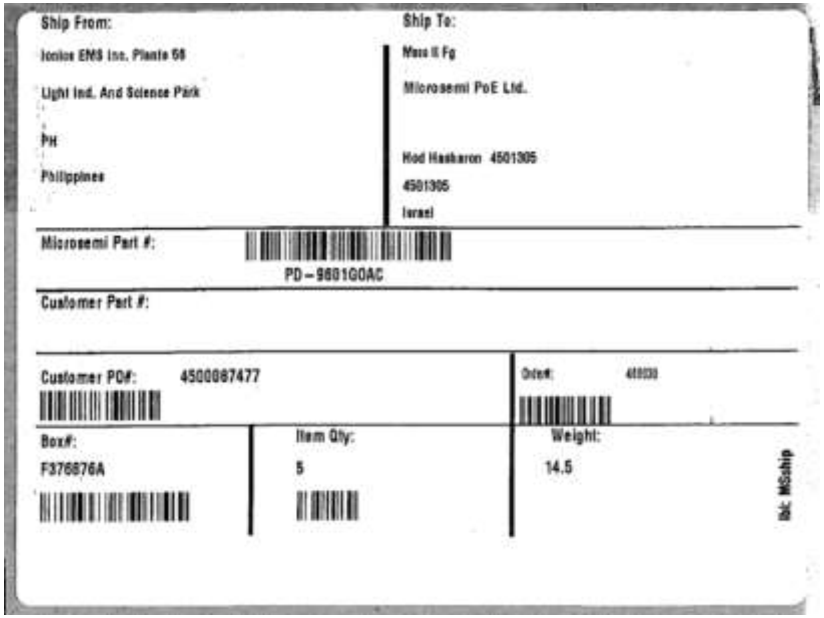
Inner Label
PoE-MCU (Buy & Resale)

PRE CHANGE			POST CHANGE		
Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode
-	-	-	MSL	Yes	No
SEALED	Yes	Yes	SEAL DATE	Yes	No
-	-	-	TRACE CODE	Yes	No
-	-	-	ID#	Yes	Yes
Microsemi	Yes	No	Microchip logo	Yes	No
RoHS	Yes	No	RoHS Symbol	Yes	No
-	-	-	China RoHS Symbol	Yes	No
-	-	-	PKG	Yes	No
-	-	-	LEAD	Yes	No
-	-	-	WAFER QTY	Yes	No
-	-	-	WAFER REV	Yes	No
-	-	-	RECERT D/C	Yes	No
2nd Lvl Intct	Yes	No	-	-	-

*2nd Lvl Intct : Manufacturer specification

Outer Label
PoE-MCU (Buy & Resale)

PRE CHANGE



Ship From:
Ionics EMS Inc. Plants 58
Light Ind. And Science Park
PH
Philippines

Ship To:
Mass II Fg
Microsemi PoE Ltd.
Hod Hasharon 4501305
4501305
Israel

Microsemi Part #: PD-9601G0AC

Customer Part #:

Customer PO#: 4500087477

Order#: [illegible]

Box#: F376876A

Item Qty: 5

Weight: 14.5

lbl: MSship

POST CHANGE

B-HK-PHC-S2269812

SHIP TO:
PHILIPS CONSUMER ELECTRONICS
WILSON LOGISTIC CT, 6/F
PHILIPS IND BLDG., 24-28 KUNG
KUNG YIP ST, KWAICHUNG
HONG KONG

Cust. P/N: 3139 227 01992

Catalog P/N: DSPIC33FJ128MC510T-I/PTC22

PO#: 55016400/2

SO #: 472542/26

Qty: 200000

Hong Kong
10-21-2010
(mm-dd-yyyy)

Carton 1 of 20
19.5 kgs

Outer Label
PoE-MCU (Buy & Resale)

PRE CHANGE			POST CHANGE		
Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode
SHIP FROM	Yes	No	-	-	-
SHIP TO	Yes	No	SHIP TO	Yes	No
Customer PO#	Yes	Yes	PO#	Yes	Yes
Customer Part#	Yes	Yes	Cust P/N	Yes	Yes
Microsemi Part#	Yes	Yes	Catalog P/N	Yes	Yes
Order#	Yes	Yes	SO#	Yes	Yes
	-	-	(mm-dd-yyyy)	Yes	No
BoX#	Yes	Yes	-	-	-
Item Qty	Yes	Yes	No of carton	Yes	No
-	-	-	eCAT Symbol	Yes	No
-	-	-	Pb Free Symbol	Yes	No
-	-	-	RoHS Symbol	Yes	No
-	-	-	China RoHS Symbol	Yes	No
-	-	-	Ship Number	Yes	Yes
-	-	-	2D barcode	No	Yes
Weight	-	-	Gross Weight	Yes	No

Moisture Sensitive Caution Label PoE-MCU (Buy & Resale)

PRE CHANGE

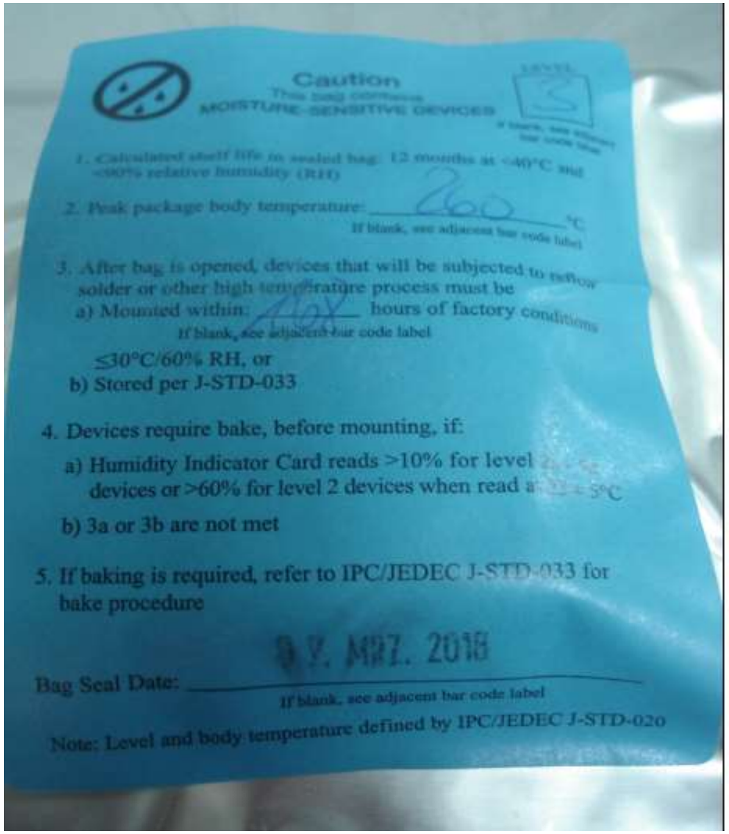
No Moisture Sensitive caution label for Moisture sensitive product

POST CHANGE

MSL Label on bag
PoE-MCU (Buy & Resale)

PRE CHANGE

<u>Future</u>



Caution
This bag contains
MOISTURE-SENSITIVE DEVICES

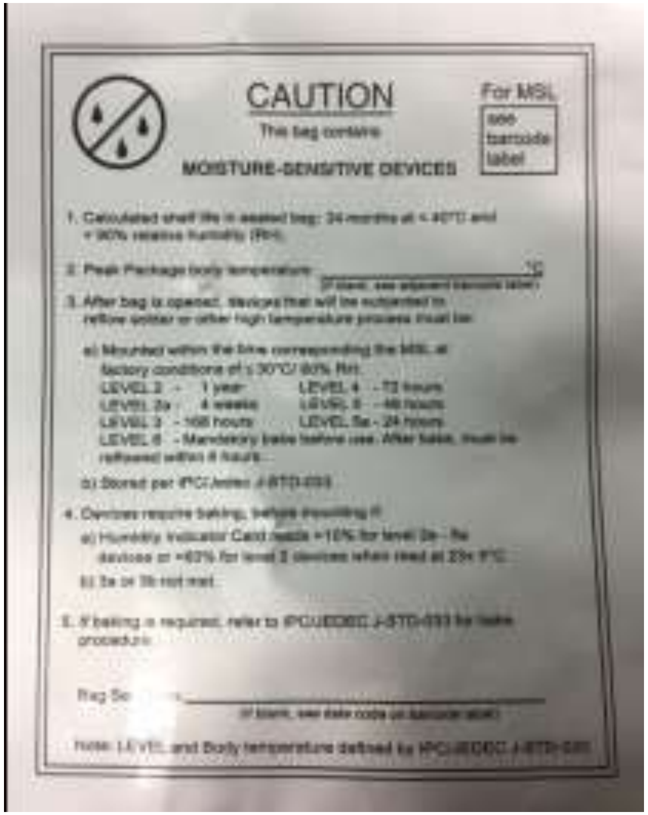
LEVEL 3
If blank, see adjacent bar code label

1. Calculated shelf life in sealed bag: 12 months at <40°C and <90% relative humidity (RH)
2. Peak package body temperature: 260 °C
   If blank, see adjacent bar code label
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be
   a) Mounted within: 168 hours of factory conditions
   If blank, see adjacent bar code label
   ≤30°C/60% RH, or
   b) Stored per J-STD-033
4. Devices require bake, before mounting, if:
   a) Humidity Indicator Card reads >10% for level 2a - 5a devices or >60% for level 2 devices when read at 23 ± 5°C
   b) 3a or 3b are not met
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure

Bag Seal Date: 09. MRZ. 2018
If blank, see adjacent bar code label

Note: Level and body temperature defined by IPC/JEDEC J-STD-020

POST CHANGE



CAUTION
This bag contains
MOISTURE-SENSITIVE DEVICES

For MSL
see barcode label

1. Calculated shelf life in sealed bag: 24 months at < 40°C and < 90% relative humidity (RH)
2. Peak Package body temperature: °C
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be
   a) Mounted within the time corresponding the MSL at factory conditions of ≤ 30°C/ 60% RH.
   LEVEL 2 - 1 year LEVEL 4 - 72 hours
   LEVEL 2a - 4 weeks LEVEL 5 - 48 hours
   LEVEL 3 - 168 hours LEVEL 5a - 24 hours
   LEVEL 6 - Mandatory bake before use. After bake, must be reflowed within 6 hours
   b) Stored per IPC/Jedec J-STD-033
4. Devices require baking, before mounting if:
   a) Humidity Indicator Card reads >10% for level 2a - 5a devices or >60% for level 2 devices when read at 23± 5°C
   b) 3a or 3b not met
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure

Bag Se

Note: LEVEL and Body temperature defined by IPC/JEDEC J-STD-020

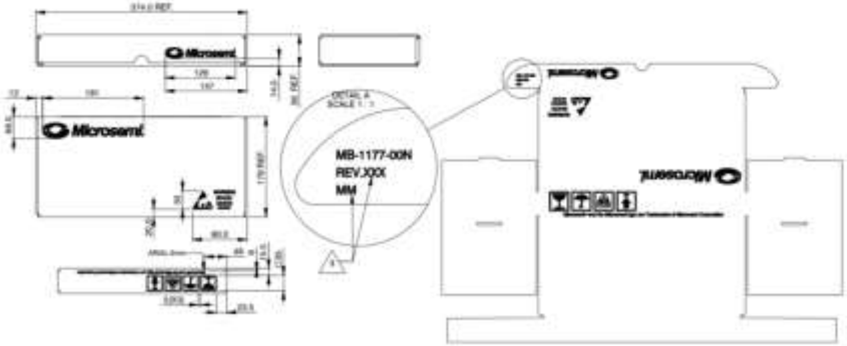
Change calculated shelf life to24 months

Tray Inner Carton
PoE-MCU (Buy & Resale)

PRE CHANGE

Ref. Dimension: W x L x H (cm)

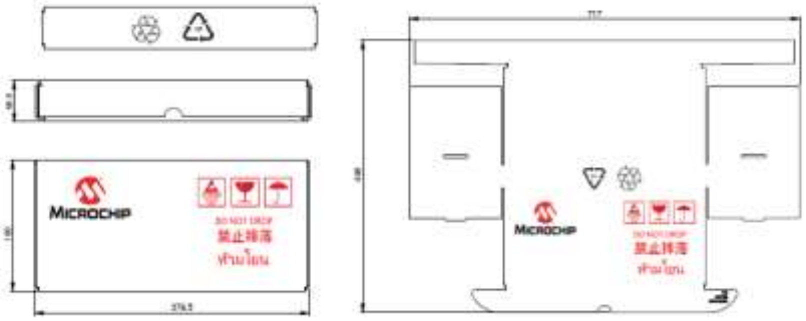
Width	Length	Height
17.9	37.14	5.6



POST CHANGE

Ref. Dimension: W x L x H (cm)

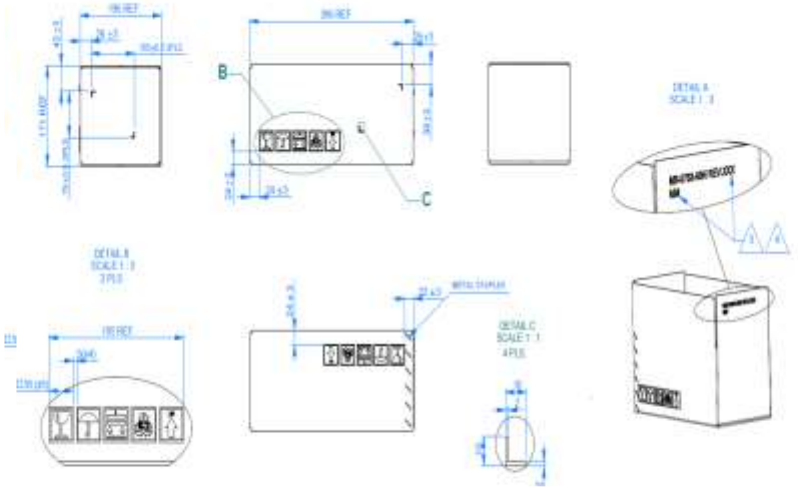
Width	Length	Height
16.2	37.1	5.0



Tray Outer Carton
PoE-MCU (Buy & Resale)

PRE CHANGE

Dimension W x L x H (cm)	**Inner : Outer**
19.0x38.4x8.2	1:1
19.0x39.0x15.9	2:1
39.0x39.0x19.6	5:1
39.0x39.0x36.5	10:1



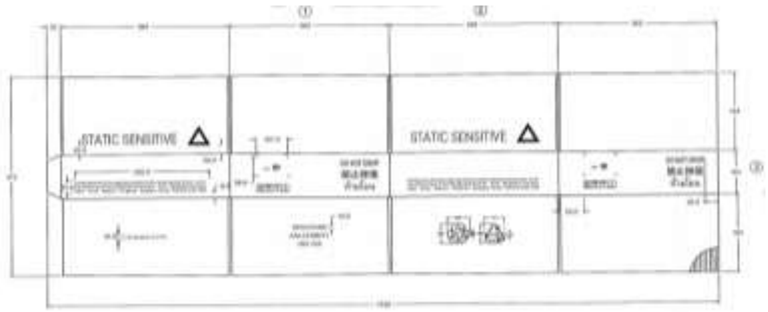
19.0x39.0x15.9	2:1

POST CHANGE

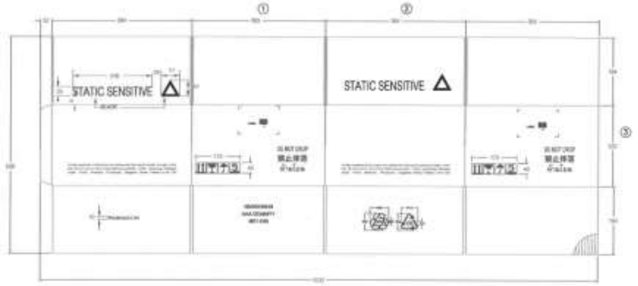
Drawing No	**Dimension W x L x H (cm)**	**Inner : Outer (Inner box for 1+1 tray stack)**
M01-044	37.0x38.0x11.0	4:1
M01-045	37.0x38.0x22.5	8:1
M01-046	37.0x39.0x39.0	12:1

Tray Outer Carton
PoE-MCU (Buy & Resale)

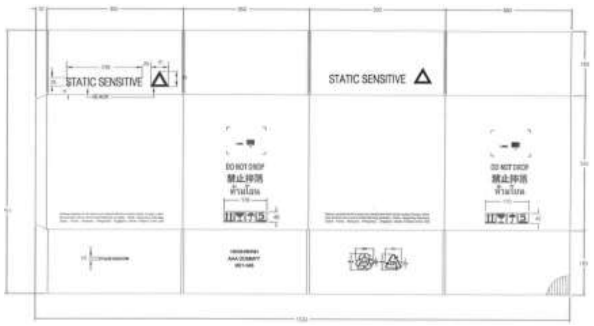
POST CHANGE



M01-044	37.0x38.0x11.0	4:1



M01-045	37.0x38.0x22.5	8:1



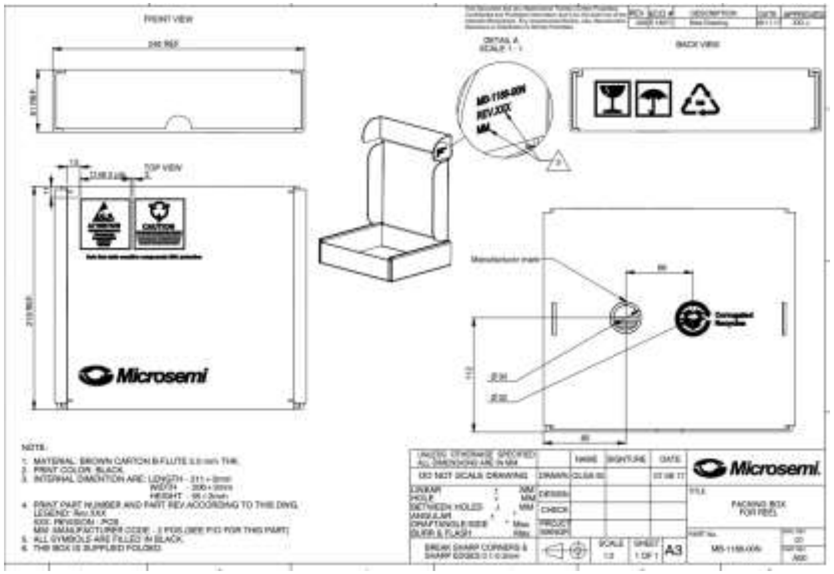
M01-046	37.0x39.0x39.0	12:1

7” T&R Inner Carton PoE-MCU (Buy & Resale)

PRE CHANGE

Ref. Dimension: (W x L x H) cm

Width	Length	Height
24.6	21.9	6.1

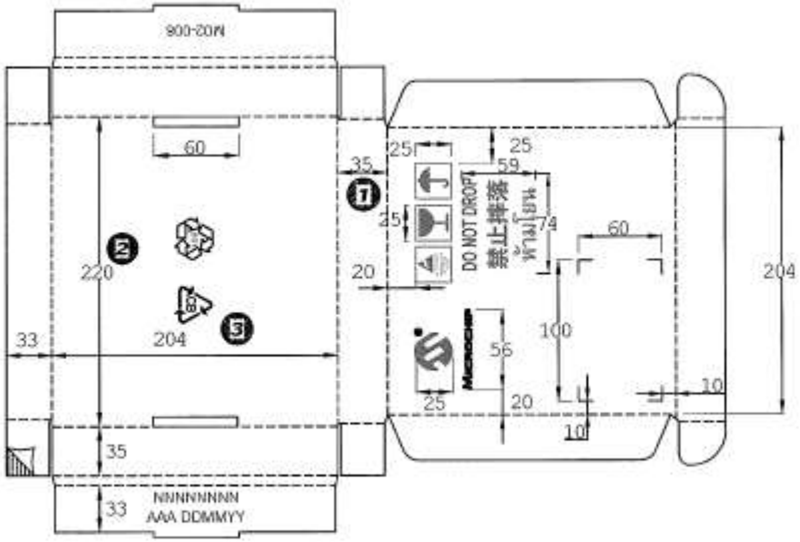


Microsemi Logo – Not must

POST CHANGE

Ref. Dimension: (W x L x H) cm

Width	Length	Height
22	20.4	3.3

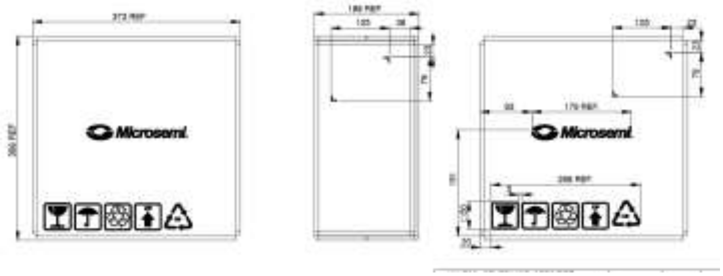


Drawing number: M02-008

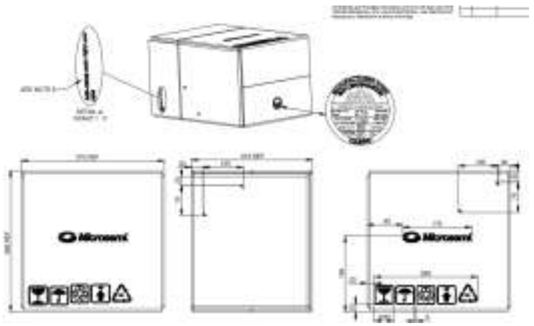
7” T&R Outer Carton
PoE-MCU (Buy & Resale)

PRE CHANGE

Dimension W x L x H (cm)	Inner : Outer
37.3x 36.8x 18.8	4 : 1
37.3x 36.8x 31.5	7 : 1



4 : 1



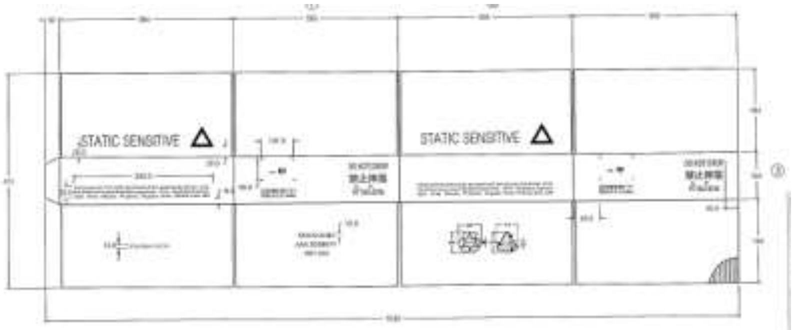
7 : 1

POST CHANGE

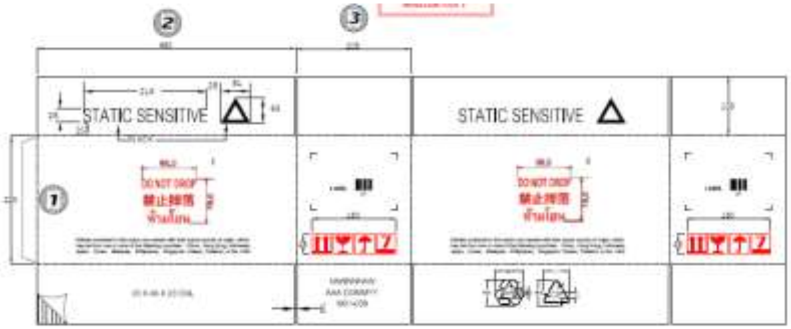
Drawing No	Dimension W x L x H (cm)	Inner : Outer
M01-044 (SM)	37.0x38.0x11.0	2 : 1
M01-112 (LO)	20.6x24.0x22.9	5 : 1
M01-038 (RT)	20x46x23	10 : 1

7” TnR Outer Carton PoE-MCU (Buy & Resale)

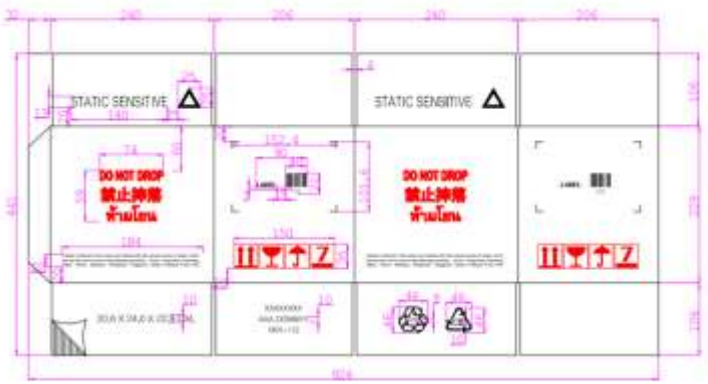
POST CHANGE



M01-044 (SM)	37.0x38.0x11.0	2 : 1



M01-038 (RT)	20x46x23	10 : 1



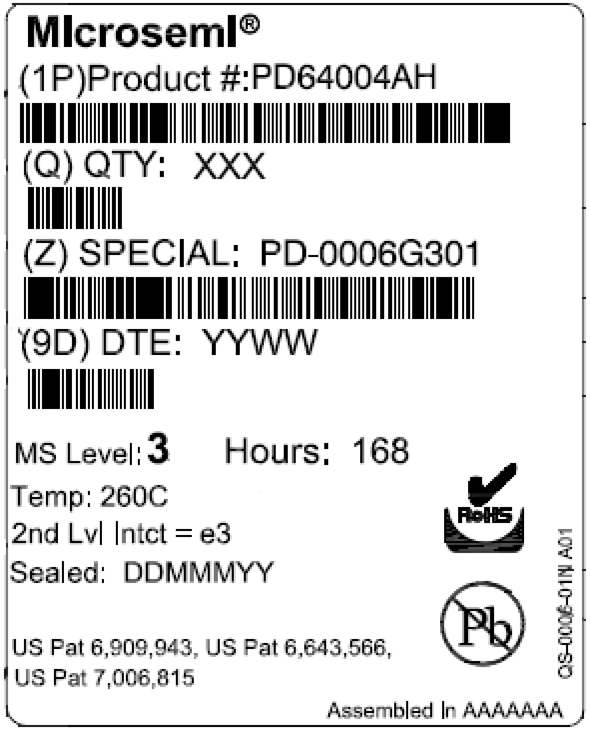
M01-112 (LO)	20.6x24.0x22.9	5 : 1

Label and Packing material change of

PoE-IC (Buy and Re-Sale)

Bag/Inner Carton Label
PoE-IC Buy and Re-sale

PRE CHANGE



Microsemi®
(1P)Product #:PD64004AH
(Q) QTY: XXX
(Z) SPECIAL: PD-0006G301
(9D) DTE: YYWW
MS Level: **3** Hours: 168
Temp: 260C
2nd Lvl Intct = e3
Sealed: DDMMMYY
RoHS
US Pat 6,909,943, US Pat 6,643,566,
US Pat 7,006,815
QS-0006-01N A01
Assembled In AAAAAAA

POST CHANGE

(1P) CATALOG P/N: **ABCDEFGKIJKL-BB-CC-DDDD-EEEEE-FF**
(1T) LOT NO.: **114601899000MTAI**
RoHS e3
MSL: 3/260 C
PKG: TFBGA
LEAD: 48
(Q) QTY
2500
(P) CUST. P/N: **ABCDEFGH IJKLMNO PQRSTUV REV A**
MPC: **ABCDEFGHKLMNO**
SEAL DATE: MM/DD/YY
WAFER QTY: -
WAFER REV: -
RECERT D/C: -
WAFER LOT: -

D/C	QTY
1407	250
1408	1000
1509	1250

ID#:(001) TRACE CODE: 1407B1R,1408B1Q,1509A3R
MADE IN THAILAND

Bag/Inner carton Label
PoE-IC Buy and Re-sale

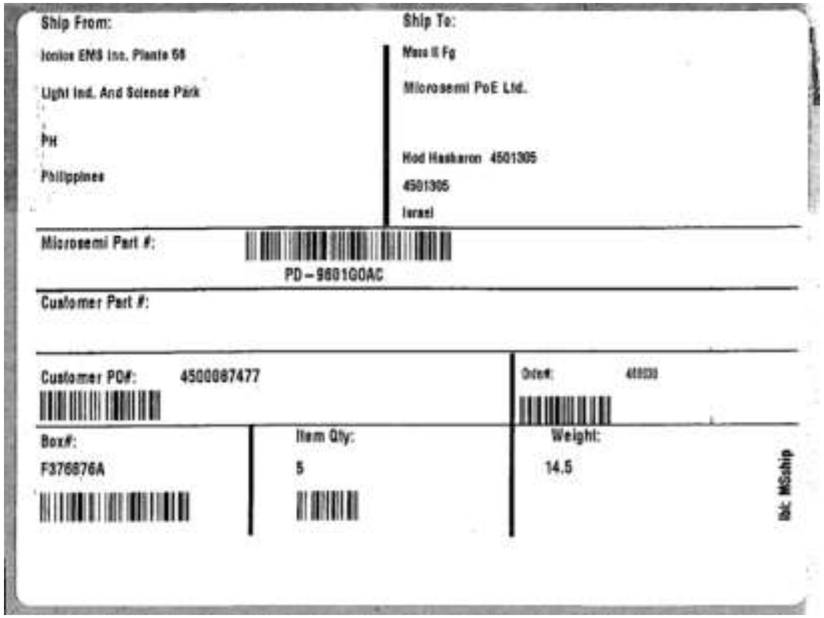
PRE CHANGE			POST CHANGE		
Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode
Microsemi	Yes	No	Microchip logo	Yes	No
(1P) PRODUCT	Yes	Yes	(1P) CATALOG P/N	Yes	Yes
(Q) QTY	Yes	Yes	(Q) QTY	Yes	Yes
(Z) SPECIAL	Yes	Yes	MPC	Yes	No
(9D) DTE	Yes	Yes	D/C	Yes	No
MSL Level	Yes	No	MSL	Yes	No
Temp	Yes	No			
2nd Lvl Intct	Yes	No	eCAT Symbol	Yes	No
Sealed	Yes	No	SEAL DATE	Yes	No
US Pat	Yes	No	-	-	-
RoHS Symbol	Yes	No	RoHS Symbol	Yes	No
Pb Free Symbol	Yes	No	Pb Free Symbol	Yes	No

Bag/Inner carton Label
PoE-IC Buy and Re-sale

PRE CHANGE			POST CHANGE		
Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode
Assembled In	Yes	No	MADE IN	Yes	No
-	-	-	(1T) LOT NO	Yes	Yes
-	-	-	QTY per D/C	Yes	No
-	-	-	(P) CUST. P/N	Yes	Yes
-	-	-	TRACE CODE	Yes	No
-	-	-	ID#	Yes	Yes
-	-	-	China RoHS Symbol	Yes	No
-	-	-	PKG	Yes	No
-	-	-	LEAD	Yes	No
-	-	-	WAFER QTY	Yes	No
-	-	-	WAFER REV	Yes	No
-	-	-	RECERT D/C	Yes	No

Outer Carton Label
PoE-IC Buy and Re-sale

PRE CHANGE



Ship From:
Ionics EMS Inc. Plants 58
Light Ind. And Science Park
PH
Philippines

Ship To:
Mass II Fg
Microsemi PoE Ltd.
Hod Hasharon 4501305
4501305
Israel

Microsemi Part #: PD-9601G0AC

Customer Part #:

Customer PO#: 4500087477

Order#: [illegible]

Box#: F376876A

Item Qty: 5

Weight: 14.5

lbl: MSship

POST CHANGE

B-HK-PHC-S2269812

SHIP TO:
PHILIPS CONSUMER ELECTRONICS
WILSON LOGISTIC CT, 6/F
PHILIPS IND BLDG., 24-28 KUNG
KUNG YIP ST, KWAICHUNG
HONG KONG

Cust. P/N: 3139 227 01992

Catalog P/N: DSPIC33FJ128MC510T-I/PTC22

Pb e0 RoHS 50

PO#: 55016400/2

SO #: 472542/26

Qty: 200000

Hong Kong
10-21-2010
(mm-dd-yyyy)

Carton 1
of 20
19.5 kgs

Outer Carton Label
PoE-IC Buy and Re-sale

PRE CHANGE			POST CHANGE		
Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode
SHIP FROM	Yes	No	-	-	-
SHIP TO	Yes	No	SHIP TO	Yes	No
Customer PO#	Yes	Yes	PO#	Yes	Yes
Customer Part#	Yes	Yes	Cust P/N	Yes	Yes
Microsemi Part#	Yes	Yes	Catalog P/N	Yes	Yes
Order#	Yes	Yes	SO#	Yes	Yes
	-	-	(mm-dd-yyyy)	Yes	No
BoX#	Yes	Yes	-	-	-
Item Qty	Yes	Yes	No of carton	Yes	No
-	-	-	eCAT Symbol	Yes	No
-	-	-	Pb Free Symbol	Yes	No
-	-	-	RoHS Symbol	Yes	No
-	-	-	China RoHS Symbol	Yes	No
-	-	-	Ship Number	Yes	Yes
-	-	-	2D barcode	No	Yes
Weight	-	-	Gross Weight	Yes	No

Moisture Sensitive Caution Label
PoE-IC Buy and Re-sale

PRE CHANGE

No Moisture Sensitive caution label for Moisture sensitive product

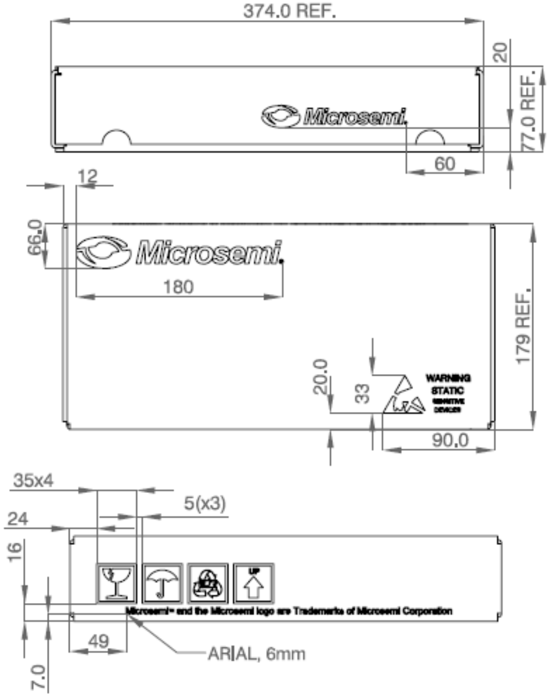
POST CHANGE

Tray Inner Carton
PoE-IC (Buy and Re-sale)

PRE CHANGE

Ref. Dimension: W x L x H (cm)

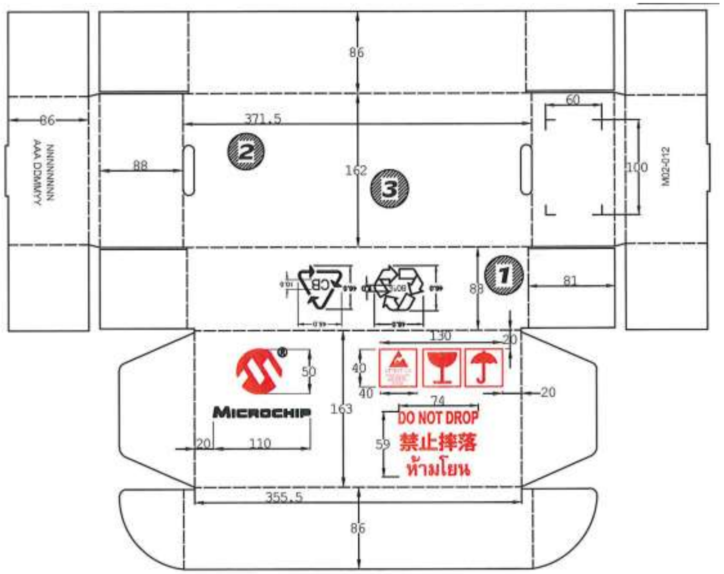
Width	Length	Height
17.9	37.14	7.7



POST CHANGE

Ref. Dimension: W x L x H (cm)

Width	Length	Height
16.2	37.1	8.8

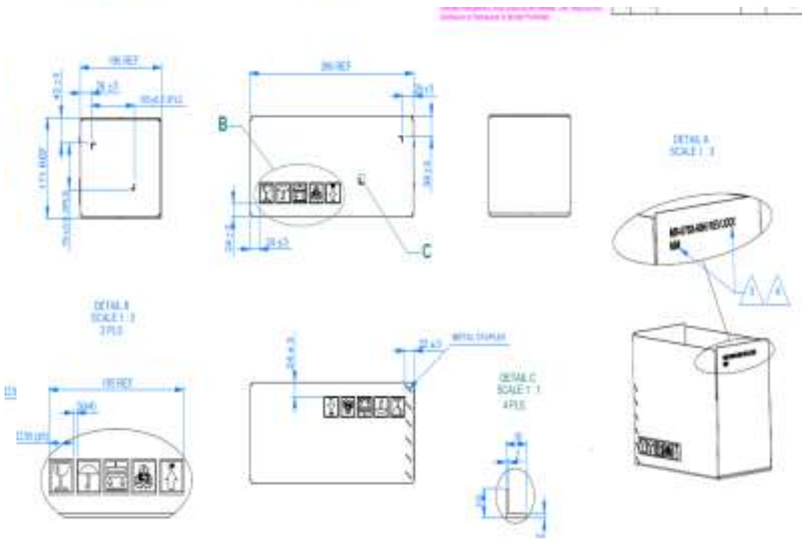


Drawing number: M02-012

Tray Outer Carton
PoE-IC (Buy & Resale)

PRE CHANGE

Dimension W x L x H (cm)	Inner : Outer
19.0x38.4x8.2	1:1
19.0x39.0x15.9	2:1
39.0x39.0x19.6	5:1
39.0x39.0x36.5	10:1



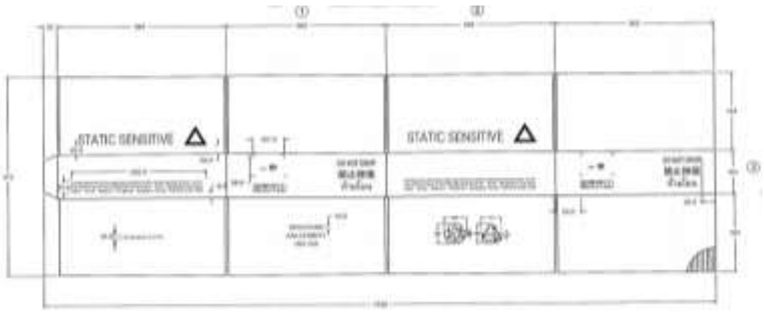
19.0x39.0x15.9	2:1

POST CHANGE

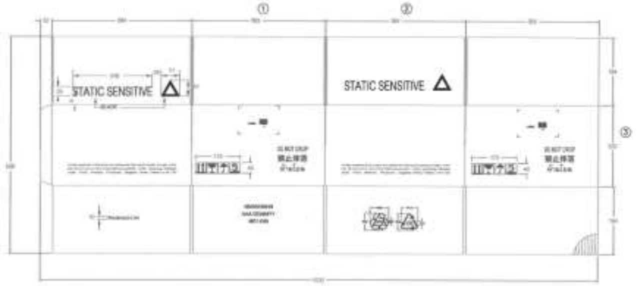
Drawing No	Dimension W x L x H (cm)	Inner : Outer
M01-044	37.0x38.0x11.0	2:1
M01-045	37.0x38.0x22.5	4:1
M01-046	37.0x39.0x39.0	8:1

Tray Outer Carton PoE-IC (Buy & Resale)

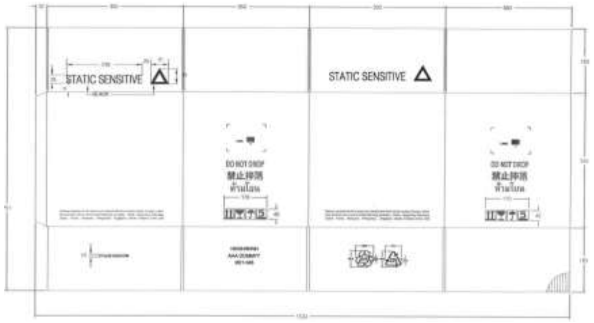
POST CHANGE



M01-044	37.0x38.0x11.0	2:1



M01-045	37.0x38.0x22.5	4:1



M01-046	37.0x39.0x39.0	8:1

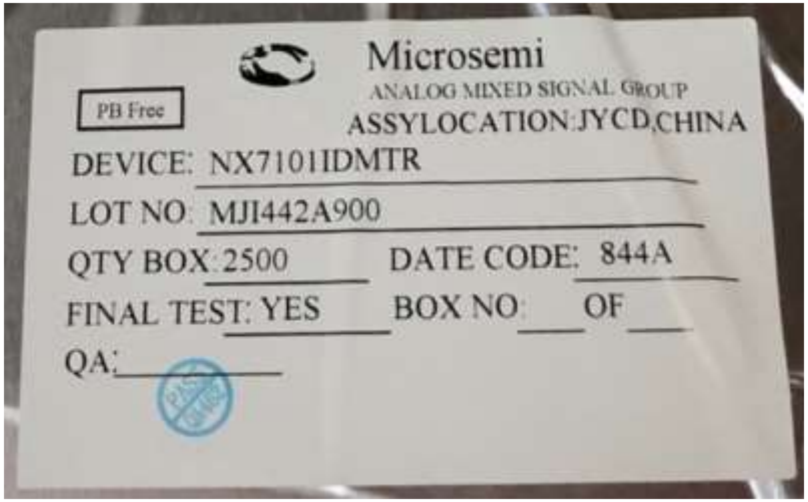
Label and Packing material change of

PM (Buy and Re-Sale)

Reel/Bag/Inner Carton Label

PM Buy and Re-sale

PRE CHANGE



Microsemi
ANALOG MIXED SIGNAL GROUP
PB Free
ASSYLOCATION:JYCD,CHINA
DEVICE: NX7101IDMTR
LOT NO: MJI442A900
QTY BOX:2500 DATE CODE: 844A
FINAL TEST: YES BOX NO: ___ OF ___
QA: ________

POST CHANGE

(1P) CATALOG P/N: **ABCDEFGKIJKL-BB-CC-DDDD-EEEEE-FF**

(1T) LOT NO.: **114601899000MTAI**

Pb RoHS e3

MSL: 3/260 C
PKG: TFBGA
LEAD: 48

(Q) QTY
2500

(P) CUST. P/N: **ABCDEFGH IJKLMNO PQRSTUV REV A**

D/C	QTY
1407	250
1408	1000
1509	1250

MPC: **ABCDEFGHKLMNO**

SEAL DATE : MM/DD/YY
WAFER QTY: -
WAFER REV: -
RECERT D/C: -
WAFER LOT: -

ID#:(001) TRACE CODE: 1407B1R,1408B1Q,1509A3R

MADE IN THAILAND

Bag/Inner carton Label
PM Buy and Re-sale

MSCC Label			MCHP Standard Label		
Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode
Pb-Free	Yes	No	Pb Free Symbol	Yes	No
Microsemi logo	Yes	No	Microchip logo	Yes	No
Assy Location	Yes	No	-	-	-
DEVICE	Yes	No	(1P) CATALOG P/N	Yes	Yes
LOT No	Yes	No	(1T) LOT NO	Yes	Yes
QTY BOX	Yes	No	(Q) QTY	Yes	Yes
DATE CODE	Yes	No	D/C	Yes	No
FINAL TEST	Yes	No	-	-	-
BOX NO	Yes	No	ID#	Yes	Yes
QA	Yes	No	-	-	-
-	-	-	MPC	Yes	No
-	-	-	RoHS Symbol	Yes	No

Bag/Inner carton Label
PM Buy and Re-sale

MSCC Label			MCHP Standard Label		
Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode
-	-	-	(QTY)	Yes	No
-	-	-	MADE IN	Yes	No
-	-	-	eCAT Symbol	Yes	No
-	-	-	(P) CUST. P/N	Yes	Yes
-	-	-	MSL	Yes	No
-	-	-	SEAL DATE	Yes	No
-	-	-	TRACE CODE	Yes	No
-	-	-	China RoHS Symbol	Yes	No
-	-	-	PKG	Yes	No
-	-	-	LEAD	Yes	No
-	-	-	WAFER QTY	Yes	No
-	-	-	WAFER REV	Yes	No
-	-	-	RECERT D/C	Yes	No

Outer Carton Label
PM Buy and Re-sale

PRE CHANGE

Microsemi
ANALOG MIXED SIGNAL GROUP

Ship From : Microsemi c/o JSI Logistics (HK) LTD
18/F, Watson Centre
16-22 Kung Yip Street
Kwai Chung, NT, HK

Ship To : ARROW CENTRAL EUROPE GMBH
C/O ARROW ELECTRONICS
TRADEPORT WEST 9461
MARCO POLOWEG 11
VENLO 5928PC
WAREHOUSE VAT NO:
NL821375118B01
VENLO
NETHERLANDS

PO#

Part Number :	Quantity :
Shipping ID :	COO :
Gross Weight :	Box Count : of

POST CHANGE

B-HK-PHC-S2269812

SHIP TO: PHILIPS CONSUMER ELECTRONICS
WILSON LOGISTIC CT, 6/F
PHILIPS IND BLDG., 24-28 KUNG
KUNG YIP ST, KWAICHUNG
HONG KONG

Cust. P/N: 3139 227 01992

Catalog P/N: DSPIC33FJ128MC510T-I/PTC22

Pb e0 RoHS 50

PO#: 55016400/2 SO #: 472542/26 Qty: 200000

Hong Kong
10-21-2010
(mm-dd-yyyy)

Carton 1
of 20
19.5 kgs

Outer Carton Label
PM Buy and Re-sale

MSCC Outer Carton Label			MCHP Shipping Box Label		
Field Name / Symbol	Human Readable	Barcode	Field Name / Symbol	Human Readable	Barcode
Ship From	Yes	No	-	-	-
Ship To	Yes	No	SHIP TO	Yes	No
PO#	Yes	No	PO#	Yes	Yes
Part Number	Yes	No	Catalog P/N	Yes	Yes
Quantity	Yes	No	QTY	Yes	Yes
Shipping ID	Yes	No	Ship Number	Yes	Yes
COO	Yes	No	-	-	-
Gross Weight	Yes	No	Gross Weight	Yes	No
Box Count	Yes	No	No of carton	Yes	No
			Cust P/N	Yes	Yes
			SO#	Yes	Yes
			(mm-dd-yyyy)	Yes	No
			eCAT Symbol	Yes	No
			Pb Free Symbol	Yes	No
			RoHS Symbol	Yes	No
			China RoHS Symbol	Yes	No
			2D barcode	No	Yes

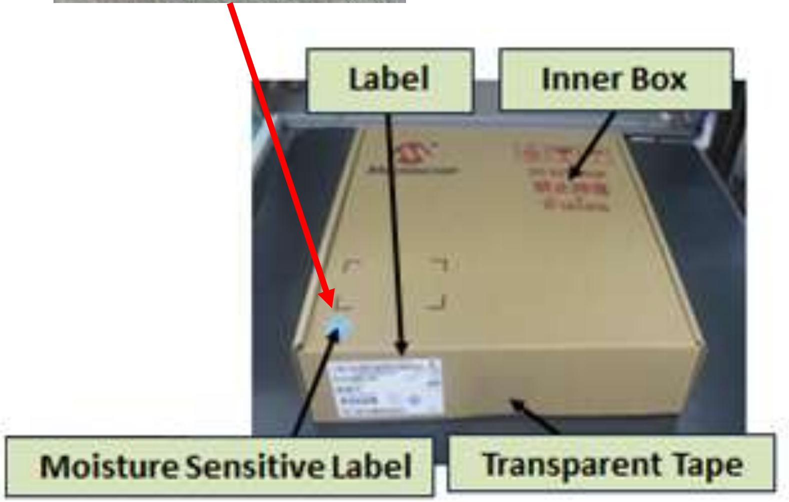
Moisture Sensitivity Identification Label
PM Buy and Re-sale

PRE CHANGE

No Moisture Sensitive caution label for Moisture sensitive product

POST CHANGE

Add MSID label to affix on inner carton for moisture sensitive device



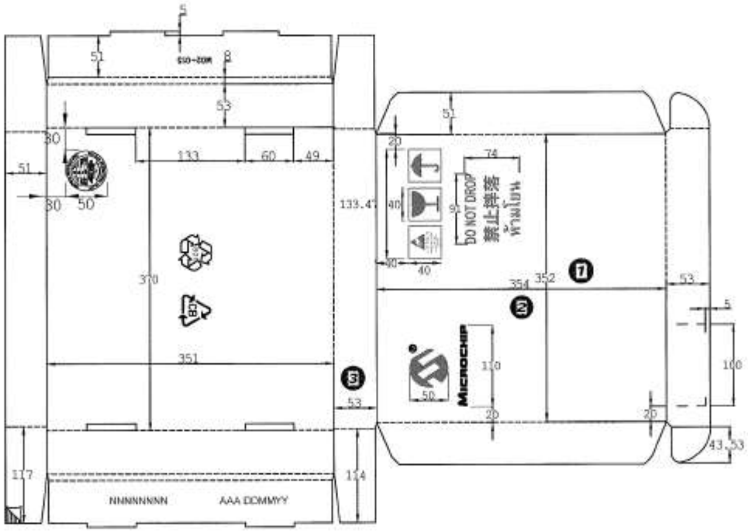
13” TnR Inner Carton
PM Buy and Re-sale

PRE CHANGE

BU	Dimension W x L x H (cm)
PM	37.0x34.5x5.5

POST CHANGE

Drawing number	Dimension W x L x H (cm)
M02-015 (Small)	37x35.1x5.3



13” TnR Outer Carton PM Buy and Re-sale

PRE CHANGE

Warehouse	Dimension W x L x H (cm)	Inner : Outer
JSI	44.0x39.0x36.5	8:1

POST CHANGE

Drawing No	Dimension W x L x H (cm)	Inner : Outer	
		M02-009 M02-015	M02-016
M01-044 (SM)	37.0x38.0x11.0	1 : 1	1 : 1
M01-045 (S4)	37.0x38.0x22.5	3 : 1	2 : 1
M01-046 (S5)	37.0x39.0x39.0	6 : 1	4 : 1
M01-047 (S3)	42.0x66.0x39.0	11 : 1	8 : 1

Label and Packing material change of CBU-Israel

Part Aging

PRE CHANGE

Microsemi may ship parts up to 24 months (2 years). Parts older than 24 months (2 years) will shipped only after prior approval from

POST CHANGE

Microchip may ship parts up to 48 months (4 years). Parts older than 24 months (2 years) old will be recertified prior to shipment. The requirement will be applied for both automotive and commercial.

Reason: Material sets used to manufacture integrated circuits have shown no degradation in solderability, moisture sensitivity or reliability of products after 48 months.

For more information related to Microchip's part aging strategy, please visit the following link on our website: Component Age Policy

Combination Rule

PRE CHANGE

- 1 Device.
- **2 Date codes.**
- No limit to number of production lots follow date code combination rule.
- 1 Assembly Site.
- 1 Test Site.
- 1 Wire Material.
- No limit for Die Revision, Die ID, Fab Revision, Different T/C, and test flow.

POST CHANGE

- 1 Device.
- **3 Date codes.**
- No limit to number of production lots follow date code combination rule.
- 1 Assembly Site.
- 1 Test Site.
- 1 Wire Material.
- No limit for Die Revision, Die ID, Fab Revision, Different T/C, and test flow.

Bag Label & Inner Label
CBU-Israel

PRE CHANGE

MSL: 4

eCAT: e1

2nd Level Interconnect

Attention:Observe Precaution for Handling ESD Devices Bag Label

(K)PURCHASE ORDER: 16241341091

(P) CUSTOMER PROD ID:

MANUFACTURER: MICROSEMI

(V) SUPPLIER CODE:

SO: 1061269

DN: 80109418

(1P)SUPPLIER PROD ID: VSC8244XHG

(1T) BATCH: T3378692

MAX TEMP: 260

(16D)SEAL DATE: 06/07/2016

(Q) QTY: 84 EA

(9D) DATE CODE: 1335

(4L) COO: TW (Taiwan)

ASSEMBLY DATE CODE: 1335BQCFC

INNER ID: 1000509272

POST CHANGE

(1P) CATALOG P/N: ABCDEFGKIJKL-BB-CC-DDDD-EEEEE-FF

(1T) LOT NO.: 114601899000MTAI

RoHS e3

MSL: 3/260 C

PKG: TFBGA

LEAD: 48

(Q) QTY

2500

(P) CUST. P/N: ABCDEFGH IJKLMNO PQRSTUV REV A

MPC: ABCDEFGHKLMNO

SEAL DATE: MM/DD/YY

WAFER QTY: -

WAFER REV: -

RECERT D/C: -

WAFER LOT: -

D/C	QTY
1407	250
1408	1000
1509	1250

ID#:(001) TRACE CODE: 1407B1R,1408B1Q,1509A3R

MADE IN THAILAND

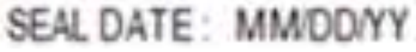
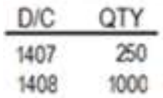
Remark:

✓ : Match information between MSCC&MCHP

🟥 : Mismatch information and require PCN

🟦 : Mismatch information but doesn't require PCN due to internal use/not customer requirement.

Bag Label & Inner Label
CBU-Israel

Field Name / Symbol	PRE CHANGE	POST CHANGE	
MAX TEMP	 MAX TEMP: 260	 MSL: 3/260 C	Remove Barcode
SEAL DATE	 (16D)SEAL DATE: 06/07/2016	 SEAL DATE : MM/DD/YY	Remove barcode And change year to “YY”
QTY	 (Q) QTY: 84 EA	 (Q) QTY 2500	Remove “EA”
DATE CODE	 (9D) DATE CODE: 1335	 D/C QTY 1407 250 1408 1000	Remove Barcode
COO	 (4L) COO: TW (Taiwan)	 MADE IN THAILAND	Remove Barcode and country code
ASSEMBLY DATE CODE	 ASSEMBLY DATE CODE: 1335BQCFC	 ID#:(001) TRACE CODE: 1407B1R,1408B1Q,1509A3R	Remove Barcode of Assembly Date * MCHP Barcode represent for Assembly lot no.+Box no.

Bag Label & Inner Label
CBU-Israel

PRE CHANGE			POST CHANGE		
Field Name / Symbol	Data format	Barcode	Field Name / Symbol	Data format	Barcode
MSL	MSLx	No	MSL	N/Peak temp	No
Pb Free Symbol	Symbol	No	Pb Free Symbol	Symbol	No
eCAT	eN	No	eCAT Symbol	Symbol	No
MSCC Address	Word	-	-	-	-
PURCHASE ODER	Number	Yes	-	-	-
CUSTOMER PROD ID	XXXXXXXXX	Yes	CUST. P/N	Customer part no.	Yes
MANUFACTURER	MICRO SEMI	Yes	-	-	-
SUPPLIER CODE	No information	Yes	-	-	-
SO	Sale Order	Yes	-	-	-
DN	Delivery Number	Yes	-	-	-

Bag Label & Inner Label
CBU-Israel

PRE CHANGE			POST CHANGE		
Field Name / Symbol	Data format	Barcode	Field Name / Symbol	Data format	Barcode
SUPPLIER PROD ID	Product ID	Yes	CATALOG P/N	CPN	Yes
BATCH	Batch No	Yes	LOT NO	BAAN Lot No	Yes
MAX TEMP	NNN	Yes	MSL	N/Peak temp	No
SEAL DATE	MM/DD/YYYY	Yes	SEAL DATE	MM/DD/YY	No
QTY	NNNNN EA	Yes	(Q) QTY	NNNNN	Yes
DATE CODE	YYNN	Yes	D/C	YYNN	No
COO	XX (Country code) + (Country Name)	Yes	MADE IN	Country Name	No
ASSEMBLY DATE CODE	XXXXXXXXX	Yes	TRACE CODE	YYWWNNN	No
INNER ID	Inner ID	Yes	ID#	(NNN)	Yes
-	-	-	Microchip logo	Logo	-

Bag Label & Inner Label

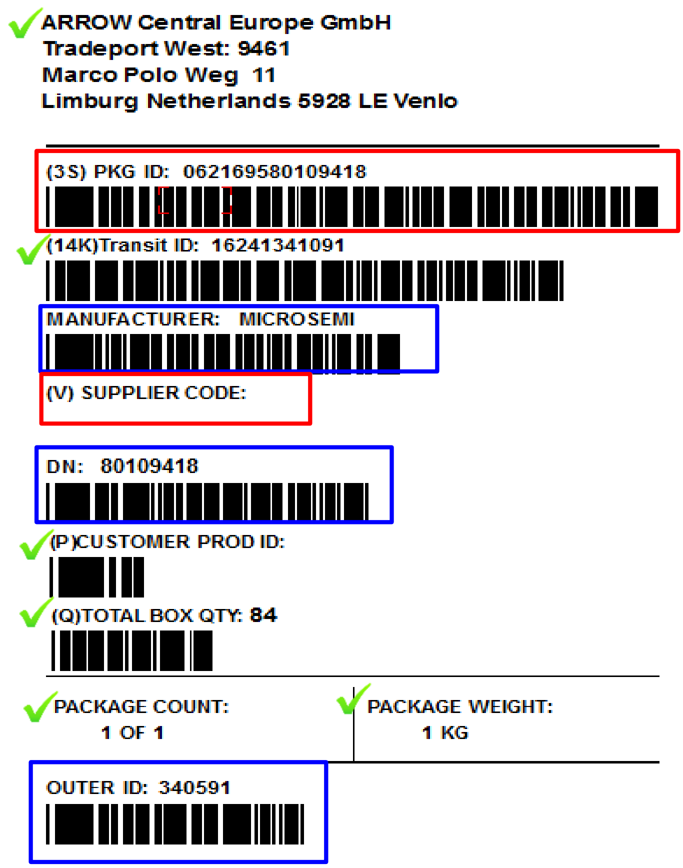
CBU-Israel

PRE CHANGE			POST CHANGE		
Field Name / Symbol	Data format	Barcode	Field Name / Symbol	Data format	Barcode
-	-	-	RoHS Symbol	Symbol	-
-	-	-	China RoHS Symbol	Symbol	-
-	-	-	PKG	Package Name	No
-	-	-	LEAD	Lead count	No
-	-	-	D/C QTY	NNNN	No
-	-	-	WAFER QTY	Wafer quantity	No
-	-	-	WAFER REV	Wafer revision	No
-	-	-	RECERT D/C	Recertification D/C	No
-	-	-	WAFER LOT	Wafer lot ID	No

Outer Label
CBU-Israel

PRE CHANGE

Outer Carton Label



✓ ARROW Central Europe GmbH
Tradeport West: 9461
Marco Polo Weg 11
Limburg Netherlands 5928 LE Venlo

(3S) PKG ID: 062169580109418

✓ (14K)Transit ID: 16241341091

MANUFACTURER: MICROSEMI

(V) SUPPLIER CODE:

DN: 80109418

✓ (P)CUSTOMER PROD ID:

✓ (Q)TOTAL BOX QTY: 84

✓ PACKAGE COUNT:
1 OF 1

✓ PACKAGE WEIGHT:
1 KG

OUTER ID: 340591

Lot No/Date Code Information Label

Outer ID : 340591

LOT NO / DATE CODE INFORMATION

(1P) Supplier Prod ID: VSC8244XHG ✓

(1T) Batch: T3378692

(11D) ASSEMBLY DATE CODE: 1335BQCFC

(4L) COO: TW Taiwan

(9D) DATE CODE: 1335

✓ (Q)Qty: 84

Box Content Label

Outer ID : 340591

Box Content Label

Customer:

ARROW Central Europe GmbH ✓

Box Details:

Gross Weight: 0.9 Kg ✓

Net Weight: 0.6 Kg

Measures: 38.6 X 18.8 X 18.8 cm

(L x W x H)

✓ Order	✓ Part No / Inner ID	✓ Qty
SO-1061269	VSC8244XHG 1000509272	84

Remark: ✓ : Match information between MSCC&MCHP

🟥 : Mismatch information and require PCN

🟦 : Mismatch information but doesn’t require PCN due to internal use/not customer requirement.

Outer Label
CBU-Israel

POST CHANGE

SHIP TO: PHILIPS CONSUMER ELECTRONICS
WILSON LOGISTIC CT, 6/F
PHILIPS IND BLDG., 24-28 KUNG
KUNG YIP ST, KWAICHUNG
HONG KONG

B-HK-PHC-S2269812

Cust. P/N: 3139 227 01992

Catalog P/N: DSPIC33FJ128MC510T-I/PTC22

PO#: 55016400/2

SO #: 472542/26

Qty: 200000

Hong Kong
10-21-2010
(mm-dd-yyyy)

Carton 1
of 20
19.5 kgs

Remark:

✓ : Match information between MSCC&MCHP

🟥 : Mismatch information and require PCN

🟦 : Mismatch information but doesn’t require PCN due to internal use/not customer requirement.

Outer Label
CBU-Israel

Field Name / Symbol	PRE CHANGE	POST CHANGE
PKG ID (Manufacture + DN)	(3S) PKG ID: 062169580109418	Remove
Supplier ID	(V) SUPPLIER CODE:	Remove
Batch	(1T) Batch: T3378692	Remove
ASSEMBLY DATE CODE	(11D) ASSEMBLY DATE CODE: 1335BQCFC	Remove
COO	(4L) COO: TW Taiwan	Remove
DATE CODE	(9D) DATE CODE: 1335	Remove
Box Details: - Net Weight - Measure (L x W x H)	Net Weight: 0.6 Kg Measures: 38.6 X 18.8 X 18.8 cm (L x W x H)	Remove

Outer Label
CBU-Israel

PRE CHANGE			POST CHANGE		
Field Name / Symbol	Data format	Barcode	Field Name / Symbol	Data format	Barcode
Ship to Address	Address	No	SHIP TO	Address	No
PKG ID (Manufacture + DN)	No information	Yes	-	-	-
Transit ID	No information	Yes	PO No.	Purchase order	Yes
MANUFACTURER	MICRO SEMI	Yes	-	-	-
SUPPLIER CODE	No information	Yes	-	-	-
DN	No information	Yes	-	-	-
CUSTOMER PROD ID	No information	Yes	Cust P/N	Customer Part Number	Yes

Outer Label
CBU-Israel

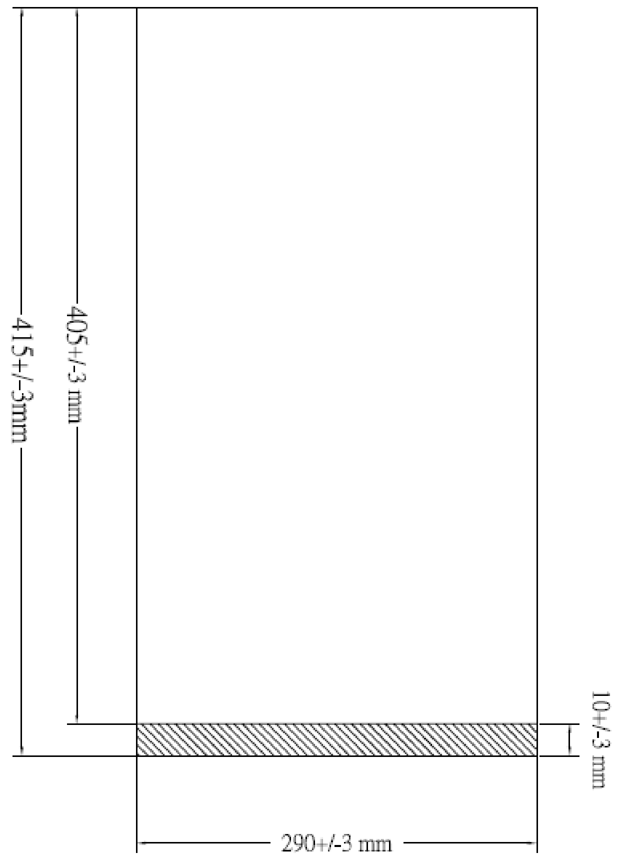
PRE CHANGE			POST CHANGE		
Field Name / Symbol	Data format	Barcode	Field Name / Symbol	Data format	Barcode
TOTAL BOX QTY	Qty in the Box	Yes	QTY	-	-
PACKAGE WEIGHT	X KG	No		XX.X kgs	No
Outer ID	Outer No.	Yes	-	-	-
Supplier Prod ID	Product ID	Yes	Catalog P/N	CPN	Yes
Batch	Batch no.	Yes	-	-	-
ASSEMBLY DATE CODE	XXXXXXXXX	Yes	-	-	-
COO	XX (Country code) + (Country Name)	Yes	-	-	-
DATE CODE	XXXX	Yes	-	-	-
QTY	NNNNN	Yes	Qty	NNNNN	Yes

Outer Label
CBU-Israel

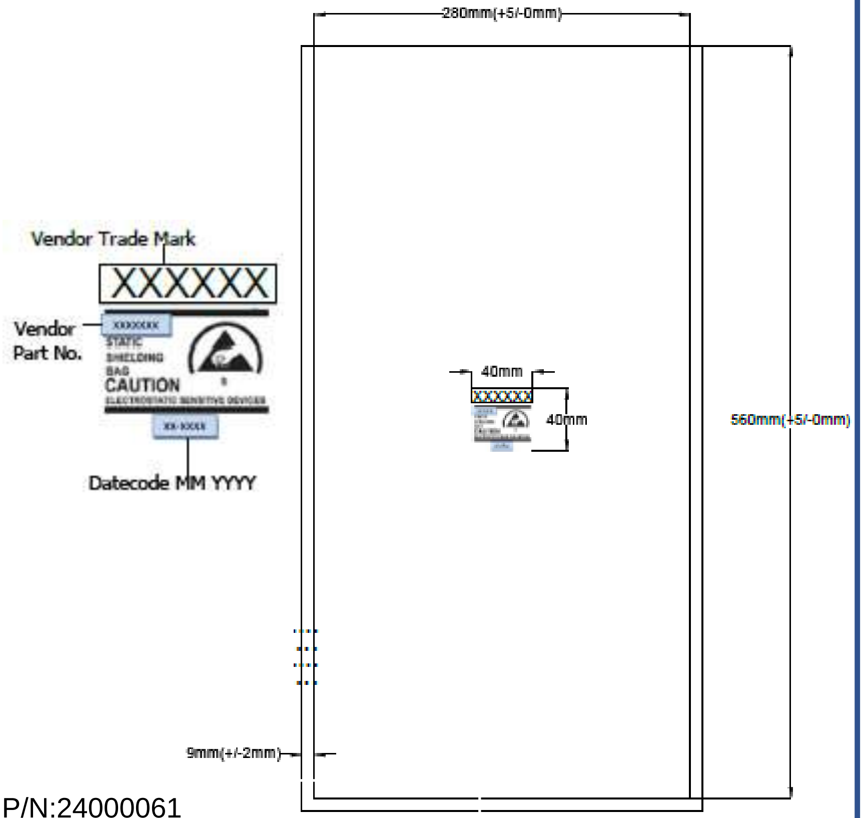
PRE CHANGE			POST CHANGE		
Field Name / Symbol	Data format	Barcode	Field Name / Symbol	Data format	Barcode
Outer ID	Outer No.	Yes	-	-	-
Customer	Customer Name	No		-	-
Box Details: - Gross Weight - Net Weight - Measure (L x W x H)		No	* Have only Gross Weight	-	-
SO	Sale Order	No	SO#	?	Yes
Part No	Part no.	No	Catalog P/N	CPN	Yes
Inner ID	Inner ID	No	-	-	-
Qty	NNNNN	No	Qty	NNNNN	Yes

Static Shield Bag (SSB) for Tray CBU-Israel

PRE CHANGE



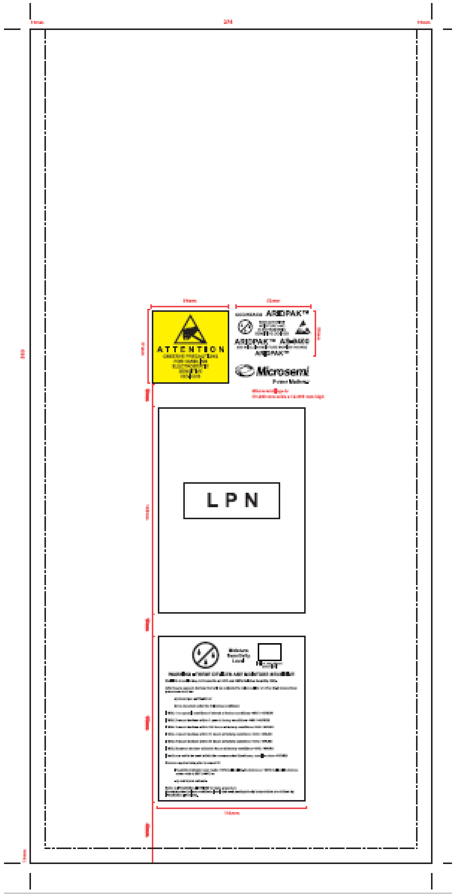
POST CHANGE



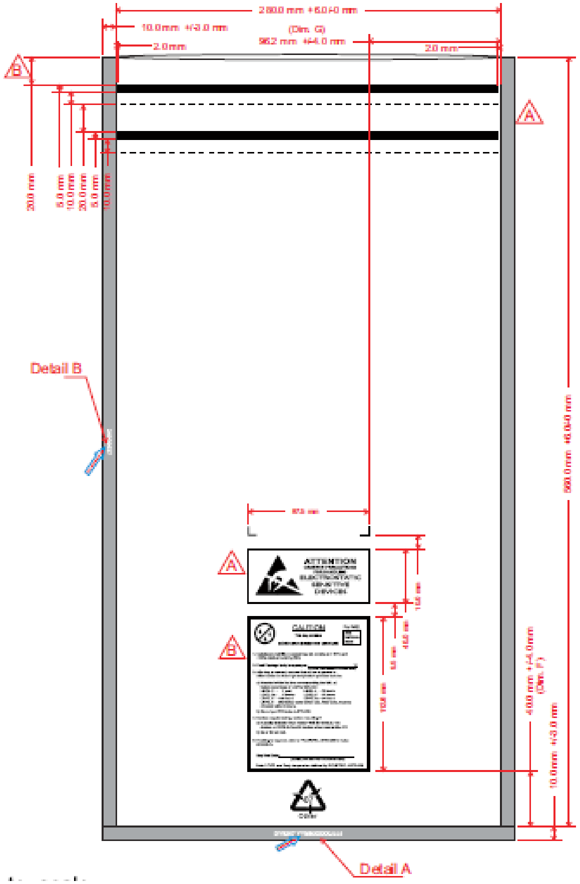
P/N:24000061
560x255

Moisture Barrier Bag (MBB) for Tray CBU-Israel

PRE CHANGE

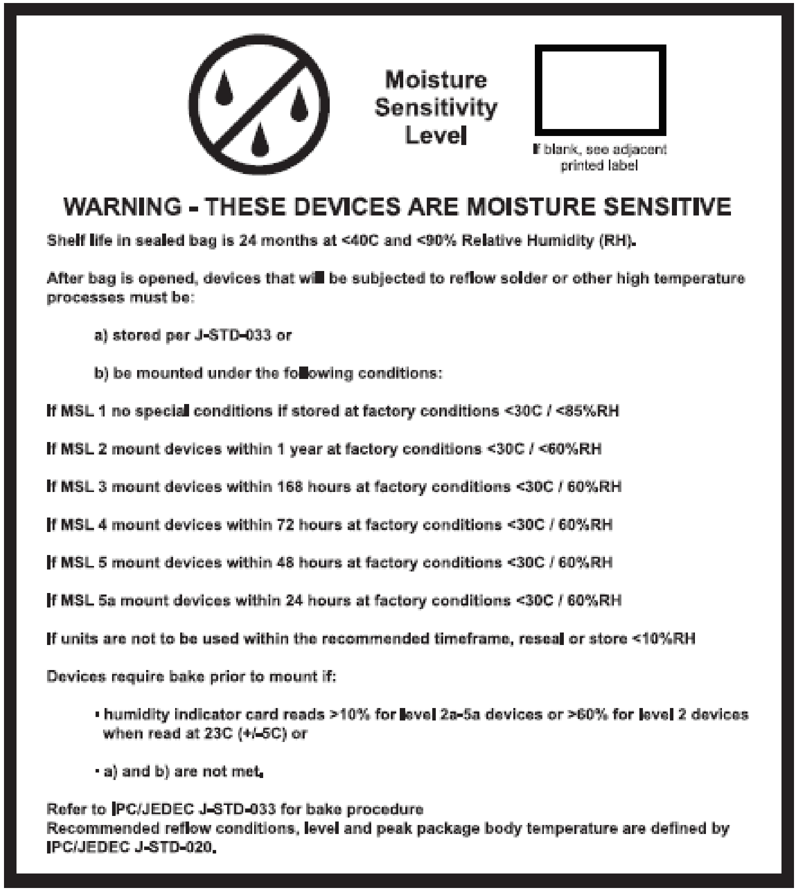


POST CHANGE



MSL Label on bag for Tray
CBU-Israel

PRE CHANGE



Moisture
Sensitivity
Level

If blank, see adjacent
printed label

WARNING - THESE DEVICES ARE MOISTURE SENSITIVE

Shelf life in sealed bag is 24 months at <40C and <90% Relative Humidity (RH).

After bag is opened, devices that will be subjected to reflow solder or other high temperature processes must be:

a) stored per J-STD-033 or

b) be mounted under the following conditions:

If MSL 1 no special conditions if stored at factory conditions <30C / <85%RH

If MSL 2 mount devices within 1 year at factory conditions <30C / <60%RH

If MSL 3 mount devices within 168 hours at factory conditions <30C / 60%RH

If MSL 4 mount devices within 72 hours at factory conditions <30C / 60%RH

If MSL 5 mount devices within 48 hours at factory conditions <30C / 60%RH

If MSL 5a mount devices within 24 hours at factory conditions <30C / 60%RH

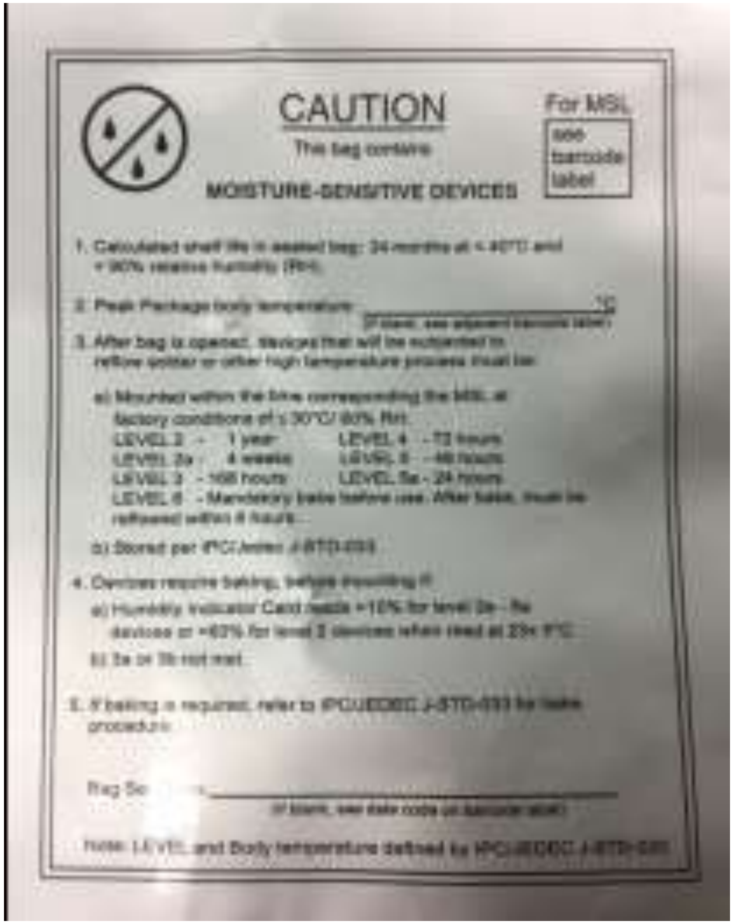
If units are not to be used within the recommended timeframe, reseal or store <10%RH

Devices require bake prior to mount if:

- humidity indicator card reads >10% for level 2a-5a devices or >60% for level 2 devices when read at 23C (+/-5C) or
- a) and b) are not met.

Refer to IPC/JEDEC J-STD-033 for bake procedure
Recommended reflow conditions, level and peak package body temperature are defined by IPC/JEDEC J-STD-020.

POST CHANGE



CAUTION

This bag contains

MOISTURE-SENSITIVE DEVICES

For MSL
see
barcode
label

1. Calculated shelf life in sealed bag: 24 months at < 40°C and < 90% relative humidity (RH).

2. Peak Package body temperature ______ °C
(If blank, see adjacent barcode label)

3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be:

a) Mounted within the time corresponding the MSL at factory conditions of ≤ 30°C/ 60% RH.
LEVEL 2 - 1 year LEVEL 4 - 72 hours
LEVEL 2a - 4 weeks LEVEL 5 - 48 hours
LEVEL 3 - 168 hours LEVEL 5a - 24 hours
LEVEL 6 - Mandatory bake before use. After bake, must be reflowed within 6 hours.

b) Stored per IPC/Jedec J-STD-033

4. Devices require baking, before mounting if:

a) Humidity Indicator Card reads >10% for level 2a - 5a devices or >60% for level 2 devices when read at 23± 5°C

b) 3a or 3b not met

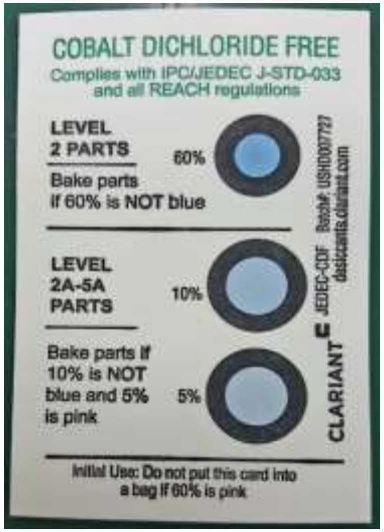
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure

Bag Se[illegible] ______
(If blank, see date code on barcode label)

Note: LEVEL and Body temperature defined by IPC/JEDEC J-STD-020

Humidity Indicator Cards (HIC) CBU-Israel

PRE CHANGE



COBALT DICHLORIDE FREE
Complies with IPC/JEDEC J-STD-033 and all REACH regulations

LEVEL 2 PARTS
Bake parts if 60% is NOT blue
60%

LEVEL 2A-5A PARTS
10%
Bake parts if 10% is NOT blue and 5% is pink
5%

Initial Use: Do not put this card into a bag if 60% is pink

CLARIANT JEDEC-CDF Batch#: USHD007727 desiccants.clariant.com

COBALT FREE
Humidity Indicator
Brown - Dry Green- Wet

LEVEL 2 PARTS
Bake parts if 60% is NOT BROWN
60%

LEVEL 2A-5A PARTS
10%
Bake parts if 10% is NOT BROWN and 5% is GREEN
5%

Initial Use: Do not put this card into a bag if 60% is green

JEDEC-CF Batch #: USHD008834
CLARIANT desiccants.clariant.com

2 HIC Types

- Cobalt Dichloride free (Non –CoCl2 type)
- Cobalt free

POST CHANGE

60% 10% 5%

LEVEL 2 PARTS
Bake parts if 60% IS NOT BROWN

LEVEL 2A-5A PARTS
Bake parts if 10% IS NOT BROWN and 5% IS AZURE

Initial use: DO NOT put this card into a bag if 5%, 10% or 60% dots are AZURE

LIGHT BROWN/BROWN-DRY AZURE-WET
COBALT FREE HUMIDITY INDICATOR
COMPLIES WITH IPC/JEDEC J-STD-033

- Cobalt free only

Desiccant
CBU-Israel

PRE CHANGE

Compliant with Mil-D-3464, TYPE II

Packing Media	No. of desiccant & bag
Tray	2 unit X 1 pouch

POST CHANGE

Compliant with Mil-D-3464, TYPEI and II

Packing Media	No. of desiccant & bag
Tray	2 units (1 unit X 2 pouches)

Moisture Sensitive Caution Label
CBU-Israel

PRE CHANGE

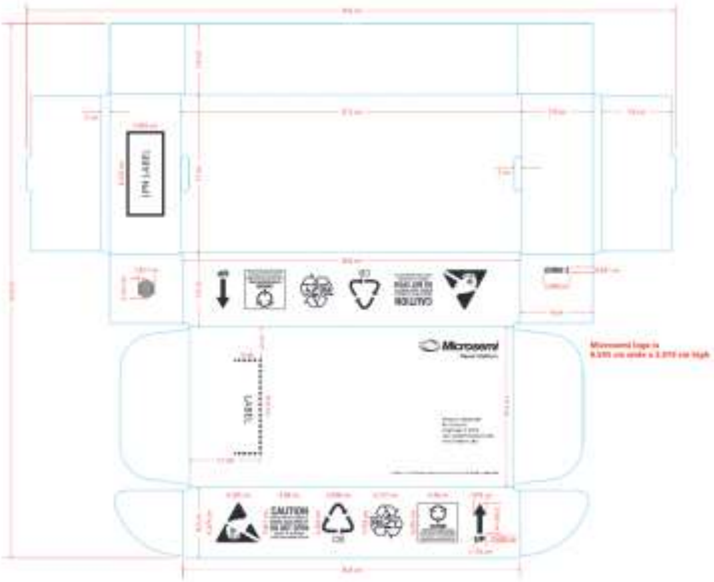
POST CHANGE

Tray Inner Carton
CBU-Israel

PRE CHANGE

Ref. Dimension: W x L x H (cm)

Width	Length	Height
17.5	37.5	8.0

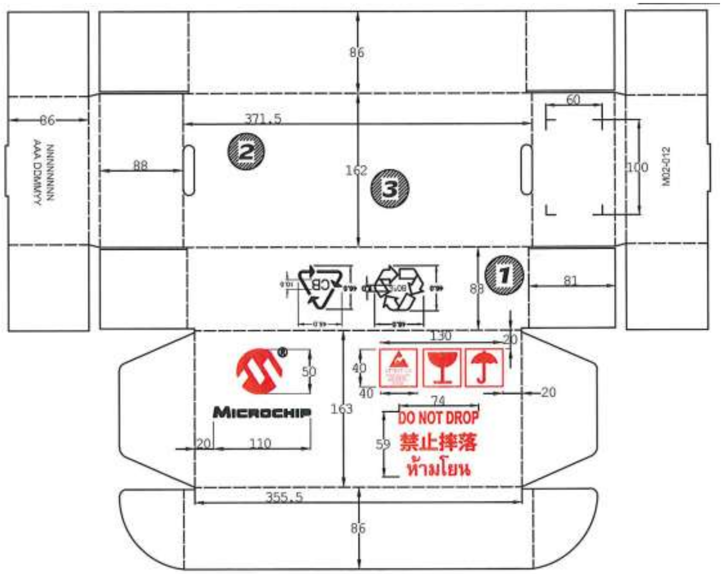


Drawing number: Microsemi_2_0_Inner_69x57cm_April_2016.pdf.

POST CHANGE

Ref. Dimension: W x L x H (cm)

Width	Length	Height
16.2	37.1	8.8



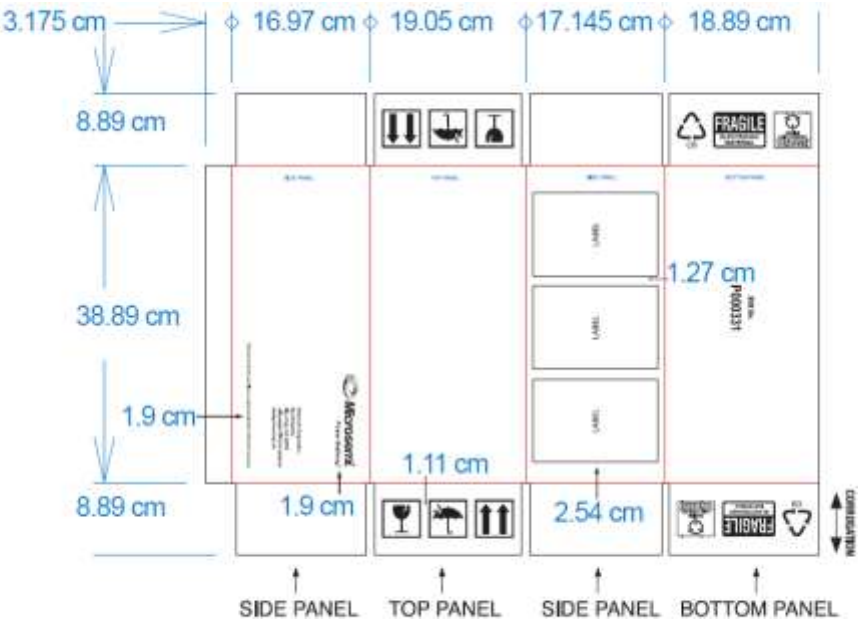
Drawing number: M02-012

Tray Outer Carton (2 Inner Carton) CBU-Israel

PRE CHANGE

Ref. Dimension: (W x L x H) cm

Width	Length	Height
19.0	40.0	18.0

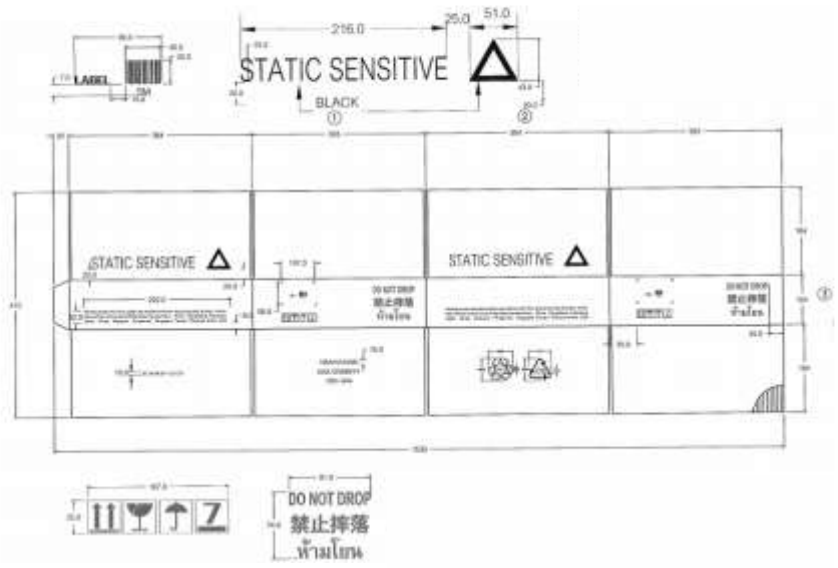


Drawing number: Microsemi_P000331_METRIC.pdf.

POST CHANGE

Ref. Dimension: (W x L x H) cm

Width	Length	Height
37.0	38.0	11.0



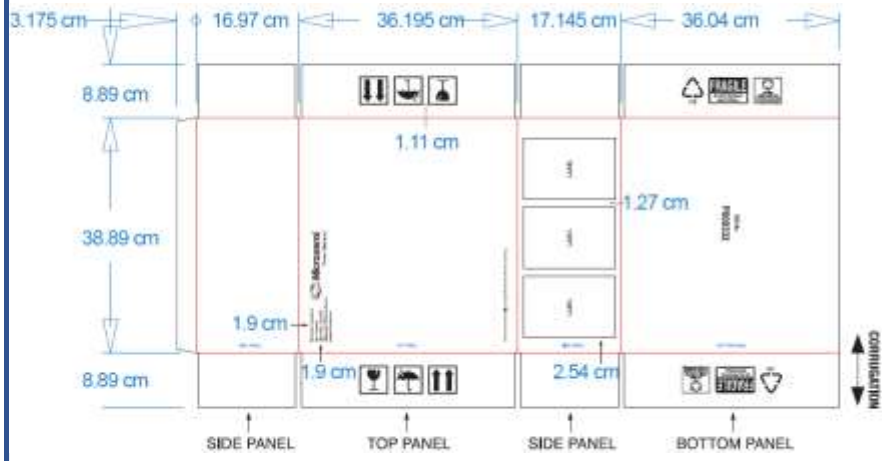
Drawing number: M01-044

Tray Outer Carton (4 Inner Carton) CBU-Israel

PRE CHANGE

Ref. Dimension: (W x L x H) cm

Width	Length	Height
36.5	40	18

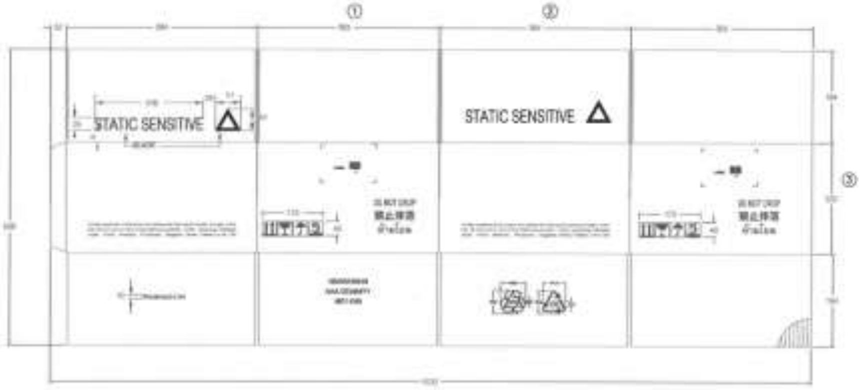


Drawing number: Microsemi_P000332_METRIC.pdf.

POST CHANGE

Ref. Dimension: (W x L x H) cm

Width	Length	Height
37.0	38.0	22.5



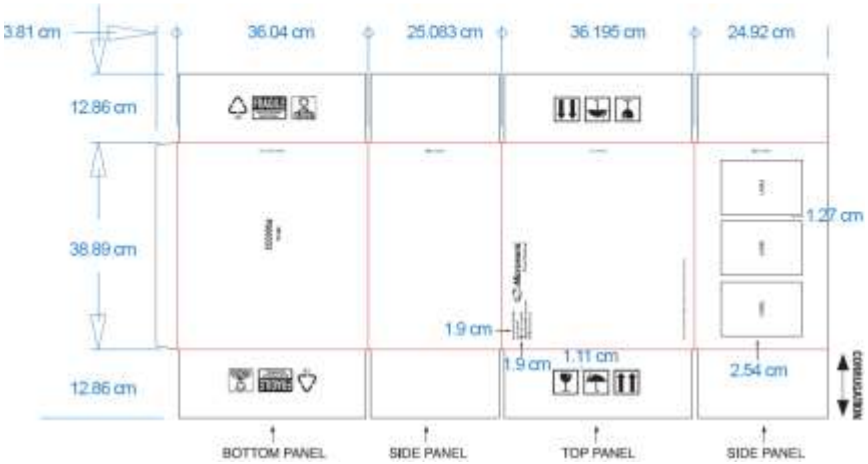
Drawing number: M01-045

Tray Outer Carton (6 Inner Carton) CBU-Israel

PRE CHANGE

Ref. Dimension: (W x L x H) cm

Width	Length	Height
36.5	38.5	25



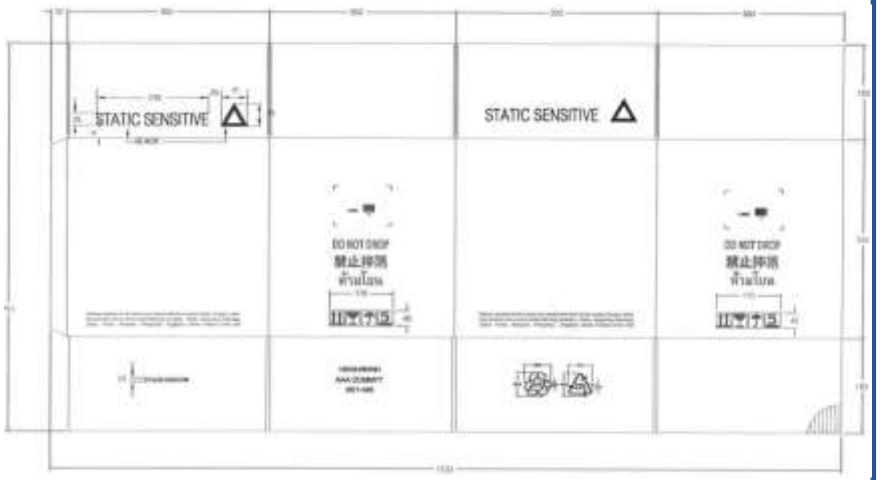
6 Pack Outer Carton

Drawing number: Microsemi_P000333_METRIC.pdf.

POST CHANGE

Ref. Dimension: (W x L x H) cm

Width	Length	Height
37.0	39.0	39.0



8 Pack Outer Carton
(6inner+2 empty inner carton)

Drawing number: M01-046

END

Frequently Asked Questions (FAQ)

Contacting Microchip: Microchip has Sales Offices Worldwide. You have received this correspondence from a Microchip Inside Sales Representative, please continue to work with him/her to guide you through the transition. Should you need to find your local office, please visit our website at: MicrochipSalesandDistribution. Also note that your current Microsemi contacts have moved to the Microchip email system therefore their email address has changed to firstname.lastname@microchip.com
You may also contact the following individuals within your geography:

Americas:	Rozita Yajadda (Rozita.yajadda@microchip.com)
Europe:	Wilson (Mary.Wilson@microchip.com)
APAC:	Nora Lee (Nora.Lee@microchip.com)
World Wide Distribution:	Jennifer Innella (Jennifer.Innella@microchip.com)
EMEA Distribution	Jane Afshar (Jane.Afshar@microchip.com)
Asia Distribution:	Derek Chan (Derek.Chan@microchip.com)

Open Direct Orders with Microsemi: Open Orders for affected parts will be transferred to the Microchip Systems on or about November 1, 2019. Customers will be contacted by local sales offices prior to the transfer to ensure a smooth transition. All orders will be transferred in US$ currency. The details of the currency conversion will be outlined by your local ISR contacts closer to the transfer date.

MOQ: Orders must be placed in multiples of tray, tube, bag, or reel size. Additionally, there may be a Purchase Order/Order Line minimum. Existing Microsemi orders being converted to Microchip orders will be subject to the Microchip base quantity multiples and Microchip Purchase Order/Order Line item minimum.
Should changes be required when migrating open backlog, each customer will be notified with full details by your local Inside Sales contact.

Order Acknowledgement: Microchip provides Acknowledgements for all new Direct orders entered and for each change made to an existing Direct order. This document is typically provided via email. Once an existing order is transferred from the Microsemi system to the Microchip system an Order Acknowledgement will then be sent. Customers or Distributors that have an EDI connection will receive either an 855 acknowledgement (US & Asia) or ORDRSP acknowledgement (Europe) via EDI.

Cancel/Reschedule: The table below provides information on the Microchip Cancel/Reschedule policy:

Catalog PN Restriction	Cancellation	CRD Push Out	CRD Pull In Allowed	CRD Push Out Allowed
Standard	>30 days PRD	>30 days PRD	Y	Y
Custom, Non Standard	>60 days PRD	>60 days PRD	Y	Y
QS9000	>60 days PRD	>60 days PRD	Y	Y
NCNR	N/A	N/A	Y	N

*CRD – Customer Requested Delivery Date
*PRD – Microchip Anticipated Delivery Date

Advanced Ship Notice (ASN): When placing a Direct Order with Microchip, customers can elect to receive an Advance Ship Notice. This document advises that your order is prepared to ship to the location identified on your Purchase Order. This option will be discussed with you by your local Microchip Contact prior to the go live date in November.

Managing Product Requirements during the Transition: The Microsemi order entry and shipments systems for items identified in this information packet will transition to Microchip systems on or about November 1, 2019. Until that time, please continue to manage your product requirements as you do today. If changes have been made with your local Representative Sales Office, please see the Microchip section **Contacting Microchip** from above. Microchip will have a 'Quiet Period' that will occur for several days surrounding the final integration so that we can import all existing Purchase Orders into our system. During that time, we will not Accept New Orders, Modify/Cancel Existing Orders, or Ship Product. Please contact your local sales office with any questions or concerns.

Shipping and Invoicing after the transition: After November 1, 2019, all products identified in this phase will be shipped and invoiced from Microchip. Please alert your **Receiving** and **Accounts Payable** departments of this change; in our experience, some clients must cancel existing backlog and then re-issue a new P.O. to Microchip. Over the coming weeks Microchip will contact you to discuss all your needs to insure there is no interruption in your supply chain.

Vendor/Supplier Code: If your system requires a new code to support order placement to Microchip and receive in Microchip shipments, please arrange as needed.

Shipping Labels, Boxes and Packing Methods: Labels, Boxes and Packing methods will be standardized to Microchip's current processes. Special shipping labels for special products such as programing products, special testing, etc. will adhere to the standard Microchip process over time. See attached Standard Microchip Label Specification.

Lots, Trace Codes, Date Codes, Part Aging, and Shelf Life: Standard Microchip methods for combining production lots, trace codes and date codes into tubes, trays, and reel media will apply as well as standard Microchip Part Aging and Shelf Life Policies. Microchip quality documents and policies including part aging policy are found on our website. QualityDocumentsandPolicies

Payment Terms: Standard payment terms are N30

Terms & Conditions: Microchip Sales are subject to the company's Terms and Conditions ("T&C"). Microchip T&C does differ slightly depending on whether the customer is in the European Union or elsewhere in the world and whether they are purchasing Direct or through microchipDIRECT. Microchip Terms and Conditions are attached.

Product/Process Change Notification (PCN) after the transition: Within the next quarters starting in November 2018 through the year 2020 and potentially into the year 2021 the standard Microchip methods for notifying customers about product changes that include PCNs and End of Life (EOL) notices will begin to apply (please note that this process will integrate over multiple phases of select products during this period). Part of the standard method includes a PCN email service that we expect to be available to select Microsemi customer/product combinations soon after each integration of select products. Once available, customers who wish to receive PCN's via email are expected to register for PCN email service on our PCN web page. Information about how and when to register will be provided in separate integration PCNs as the products you are interested in are phased in. The Microsemi PCN system will continue to be used in conjunction with a partial Microchip PCN system until the full Microchip PCN system can support Microsemi products soon after each group of products have been integrated (review how in the Microsemi Integration PCN's below). The Microsemi PCN system supporting integrated groups of products will be terminated soon after the transition to Microchip systems has completed for each product grouping. Information about Microchip's PCN system can be found at this link: Microchip PCN Website

Microsemi Integration PCN's: Until each product grouping has been integrated into Microchip's PCN system all PCN's related to the integration will be distributed using the Microsemi PCN system and can also be found at this Microchip website: Product Change Notifications. This same PCN distribution process will be used to inform customers to register for the Microchip PCN email distribution process soon after each product grouping has been integrated. Additional integration PCNs for Microsemi products may be issued for the following changes; ordering part numbering convention, shipping labels, shipping boxes, packing methods, part aging/shelf life, top marking, manufacturing site, Bill of Material (BOM), Silicon, and EOL among others.

RoHS Information: Can be found on the Microchip Website under RoHS PB Free, RoHS Device Search. An email will be generated from the system with all of the pertinent information regarding the device search.
http://www.microchip.com/wwwproducts/Rohs/